

NOTES, UNLESS OTHERWISE SPECIFIED:

1. The netname "P12V" represents connection to the +12V power plane.
2. The netname "P3P3V" represents connection to the +3.3V power plane.
3. The netname "P1P8V" represents connection to the +1.8V digital power plane.
4. The netname "P1P1V" represents connection to the +1.1V power plane.
5. The netname "P1P8V ITEA" represents connection to the +1.8V ITE6535 analog supply power plane.
6. The netname "F\_VCCIO" represents connection to the +3V FPGA Vccio power plane.
7. The netname "P2P5V\_FAUXPLL" represents connection to the +2.5V FPGA aux/pll power plane.
8. The netname "P1P8V\_A" represents connection to the +1.8V controller analog supply power plane.
9. The netname "GND" represents connection to the ground plane.
10. A "Z" suffix on a signal name indicates an active low signal.
11. All components with designators "U\*", "Q\*", and "D\*" are electrostatic discharge sensitive.



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REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
A	ECO 2137507: Initial Release	11/1/2013	NG
B	ECO 2140137: Updated to rev B	2/18/2014	NG
C	ECO 2141055: Updated to rev C	4/8/2014	NG
D	ECO 2142175: Updated to rev D	5/28/2014	NG
E	ECO 2144118: Updated to rev E	8/8/2014	NG

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		APVD L. Harvey	8/8/2014		
		MFG xxxxxxx			
2513535	0314PO	QA xxxxxxxx		TITLE ESD, Dual DLPC900 Hi-Res Main Board Reference Design	
NEXT ASSY	USED ON			<b>A3</b>	DRAWING NO 2513534
APPLICATION		SW	Cadence 16.5	SCALE	SHEET 1 of 28
					REV E

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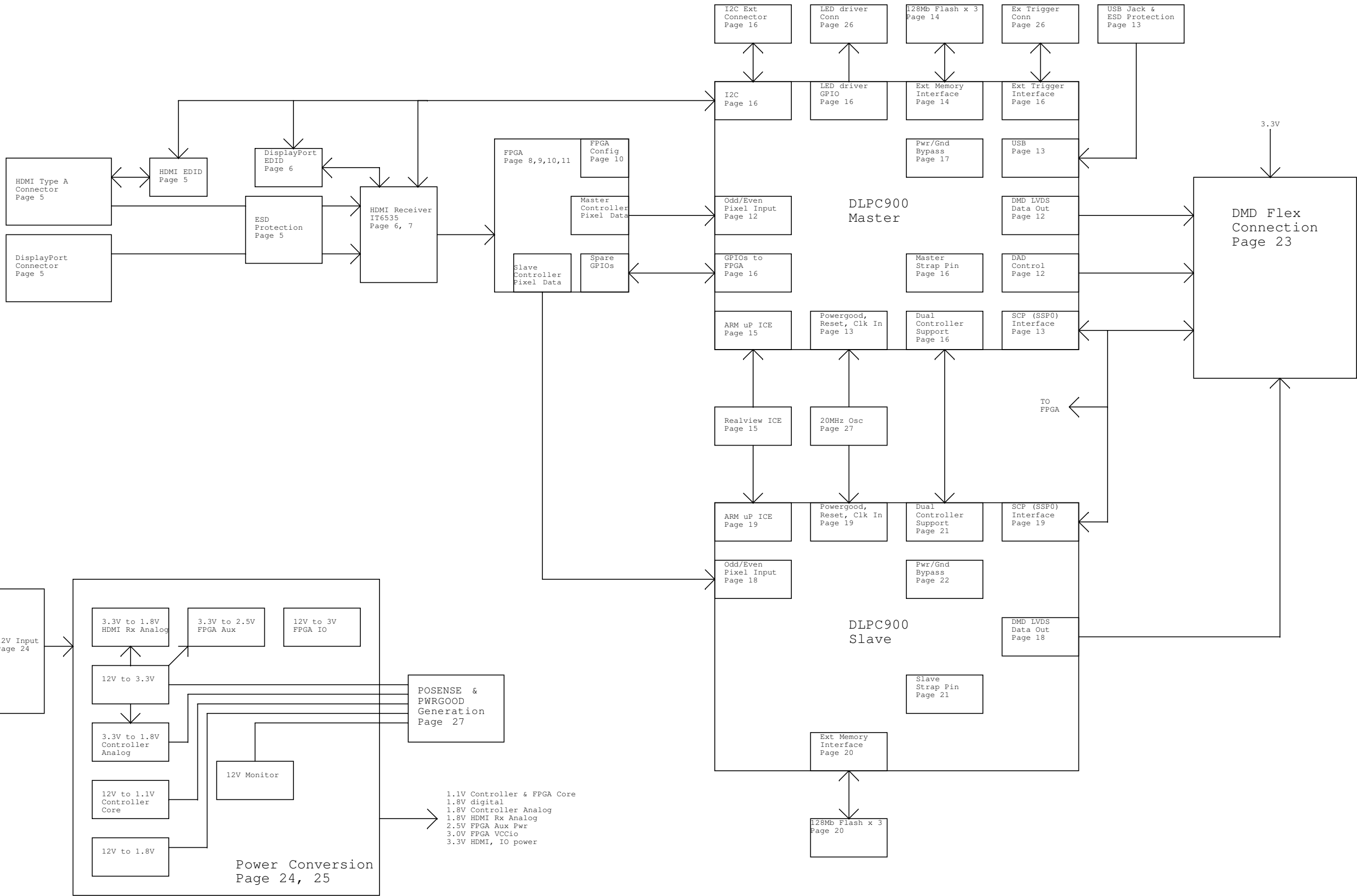
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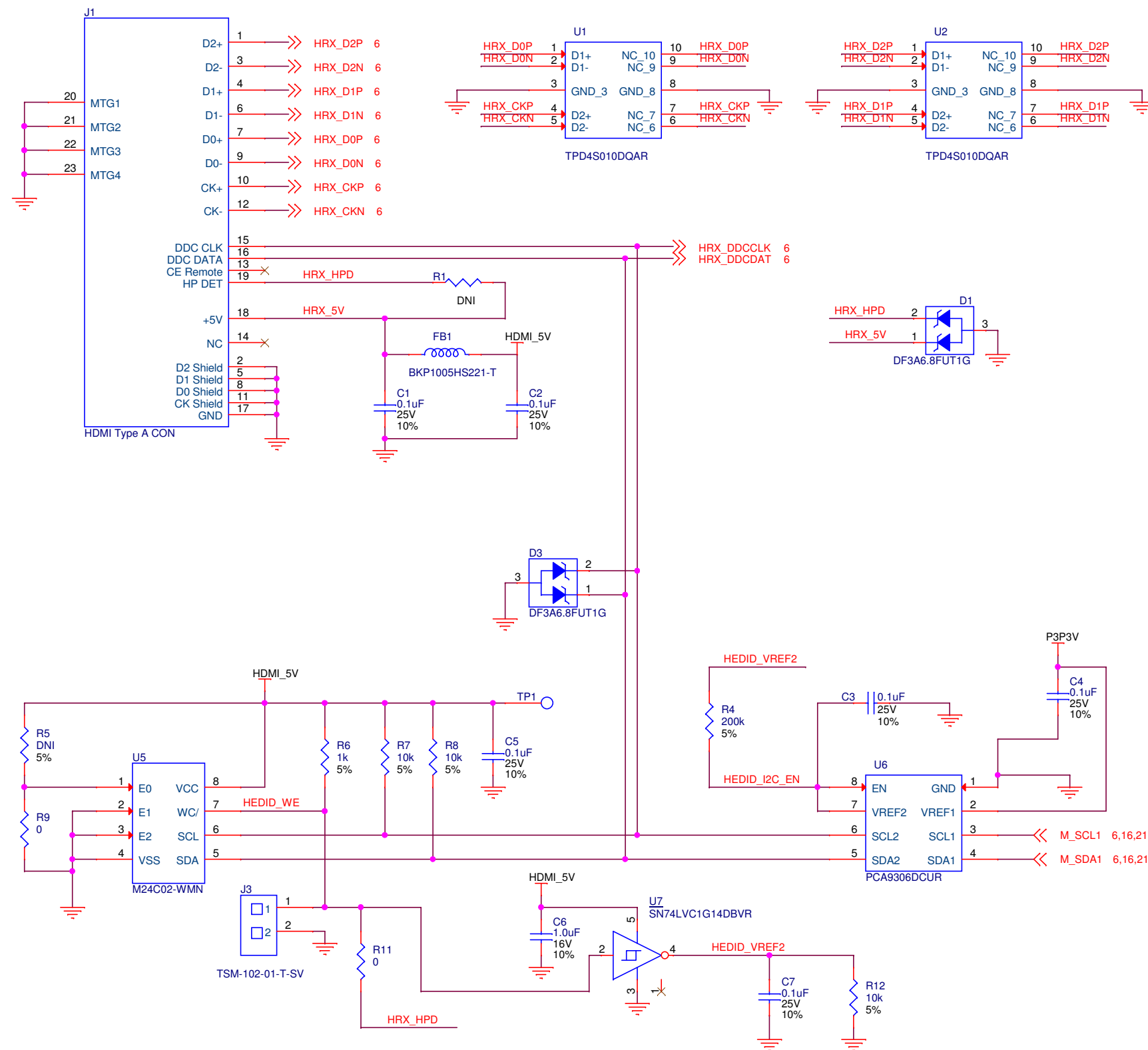
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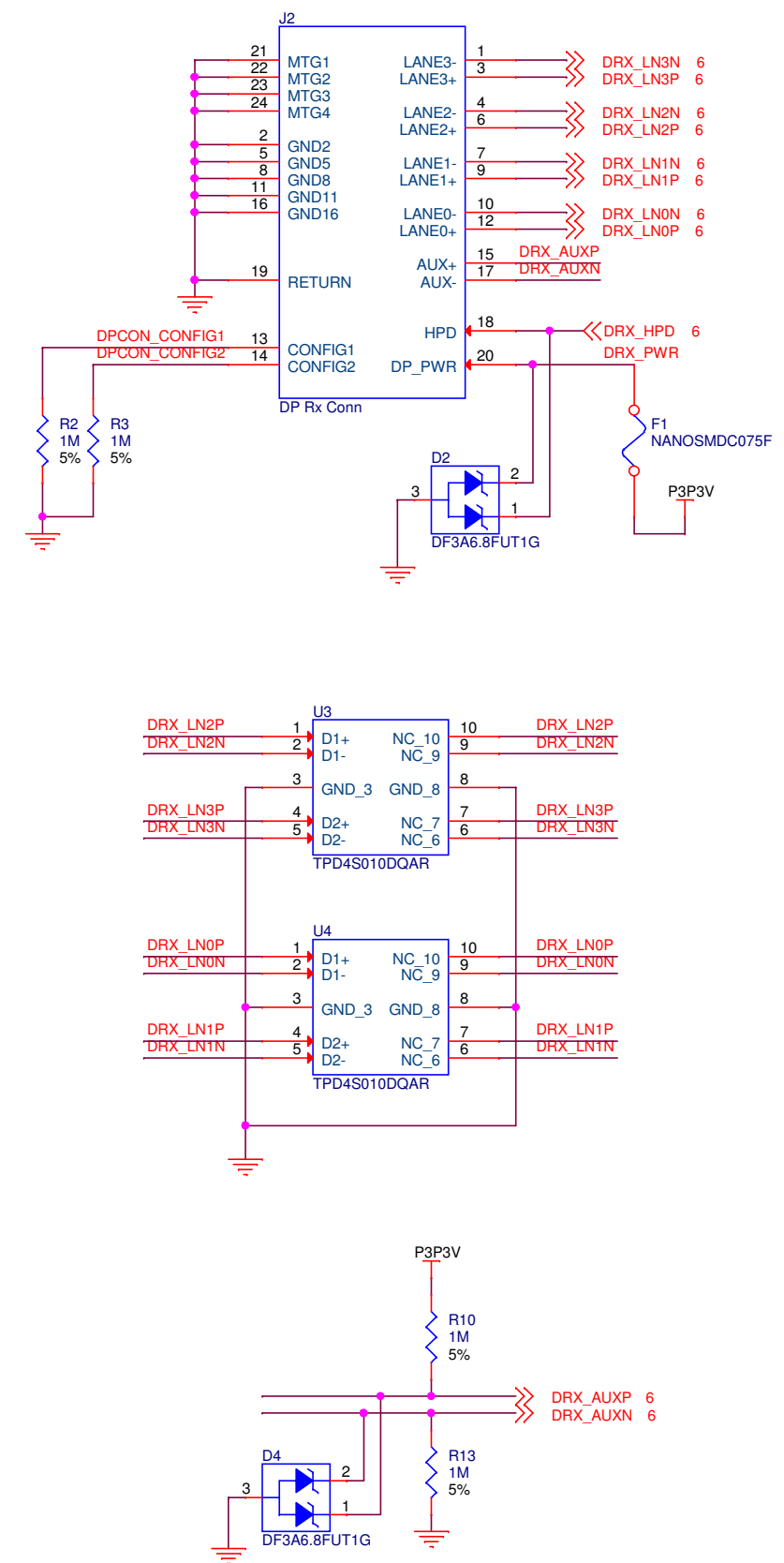




To program HDMI EDID

- install jumper to enable PROM write and disable hot plug detect
- connect HDMI cable to supply 5V
- use TI control program to update EDID

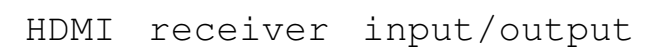
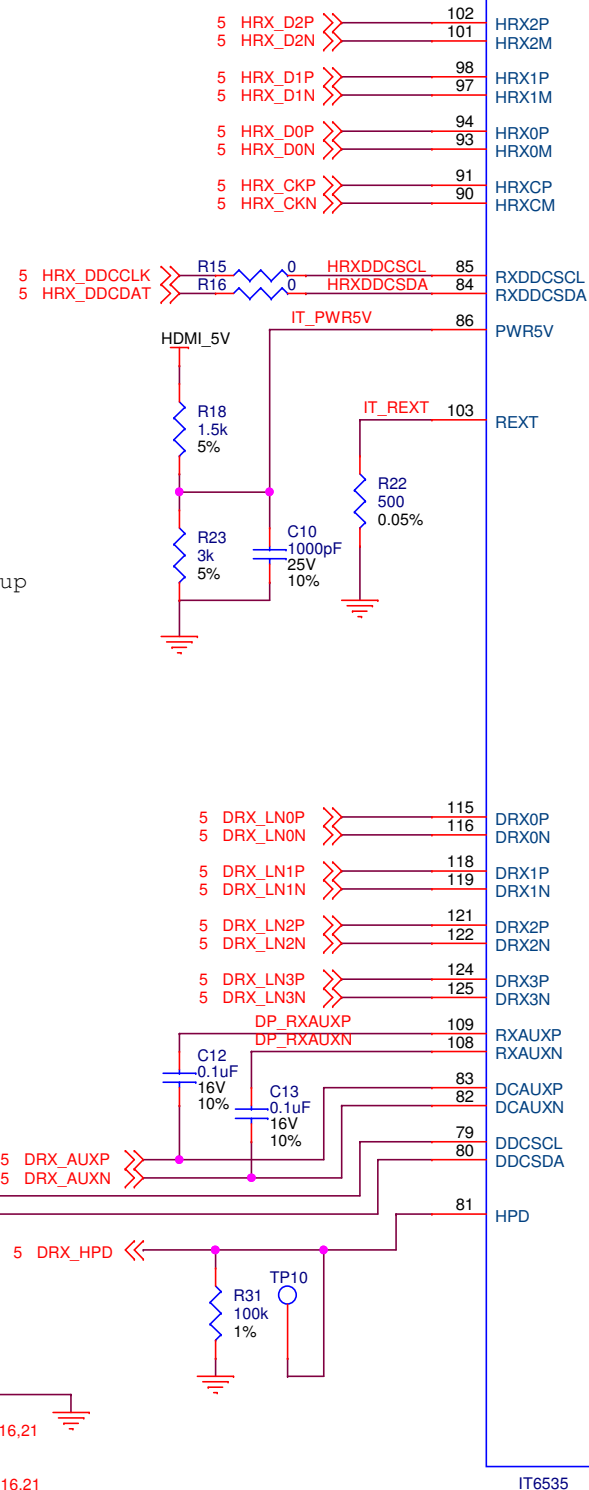
HDMI TypeA Rx Conn, ESD, and EDID

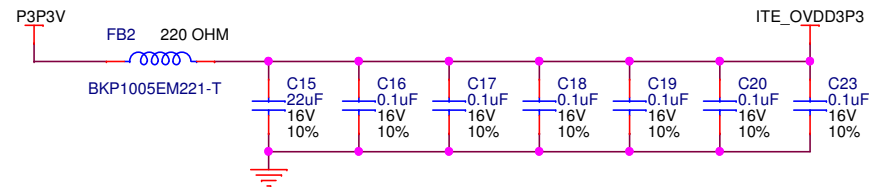
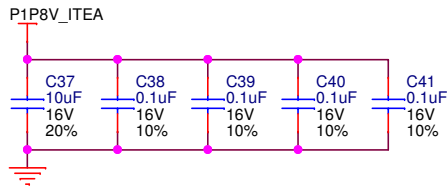
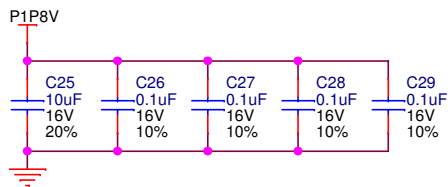
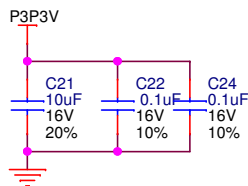


DisplayPort Rx Conn, ESD

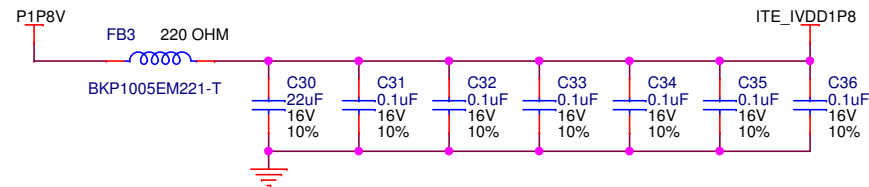
Must connect I2C and interrupt to controller for register setup

Must connect I2C and interrupt  
to controller for register setup

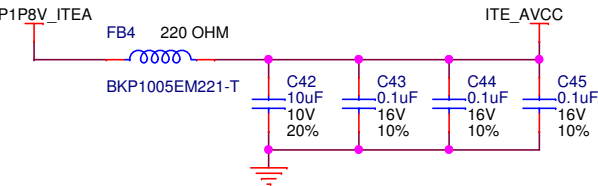




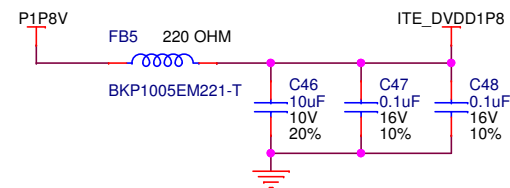
3.3V IO



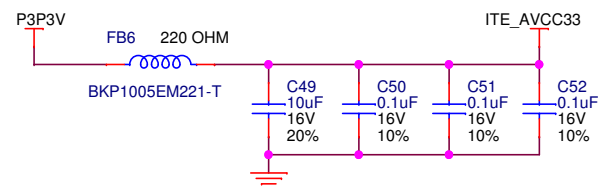
Digital logic core



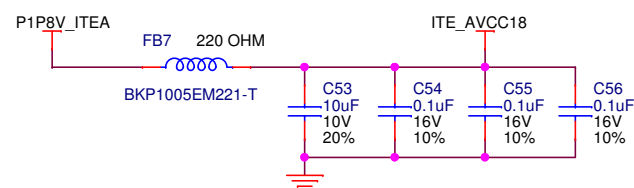
DP analog frontend



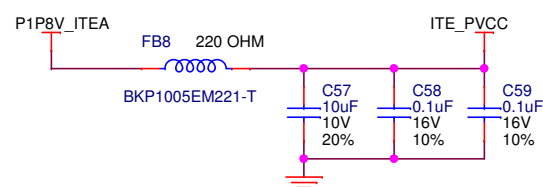
Logic power for analog frontend



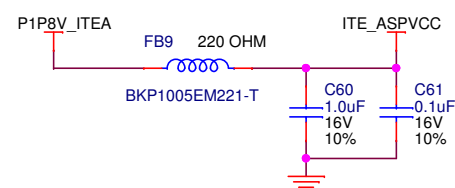
3.3V HDMI RX analog frontend



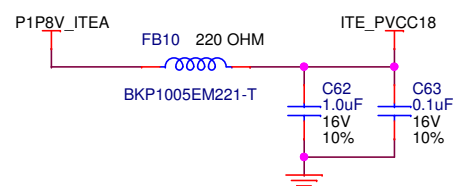
1.8V HDMI RX analog frontend



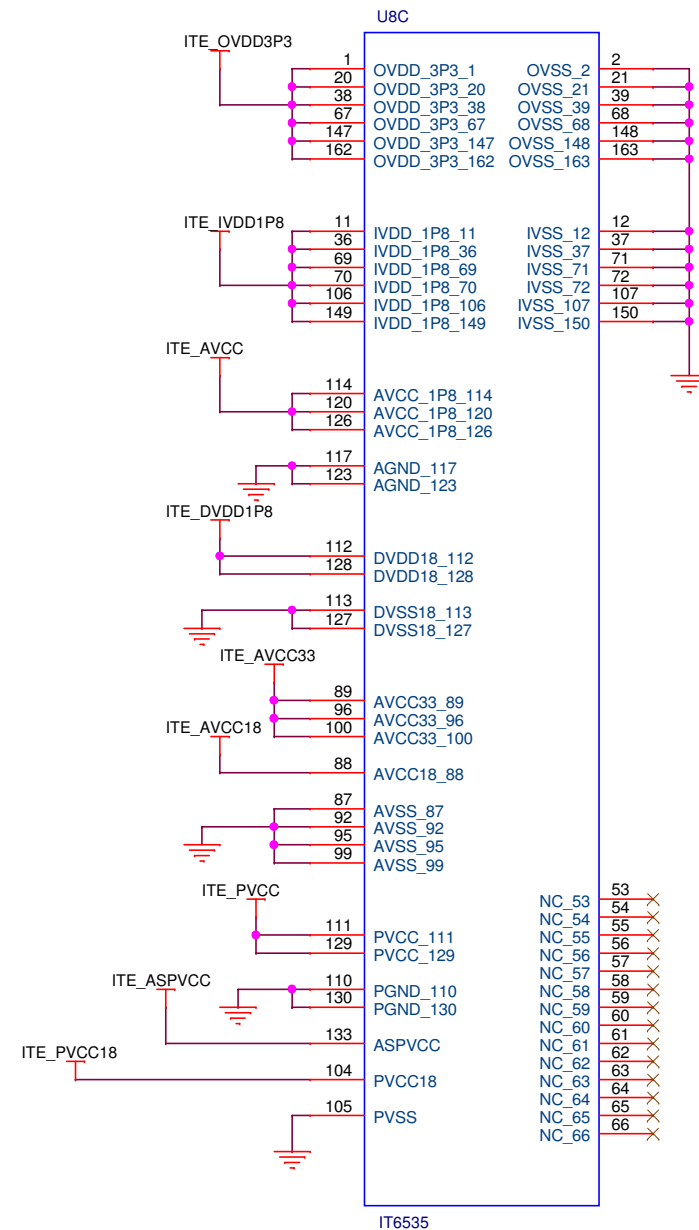
DP Rx PLL power



Crystal and audio PLL



HDMI Rx PLL power



HDMI receiver power/gnd bypass

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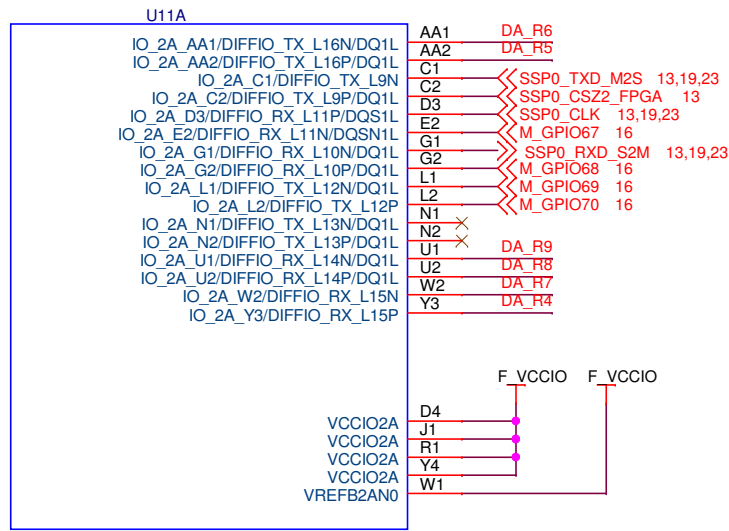
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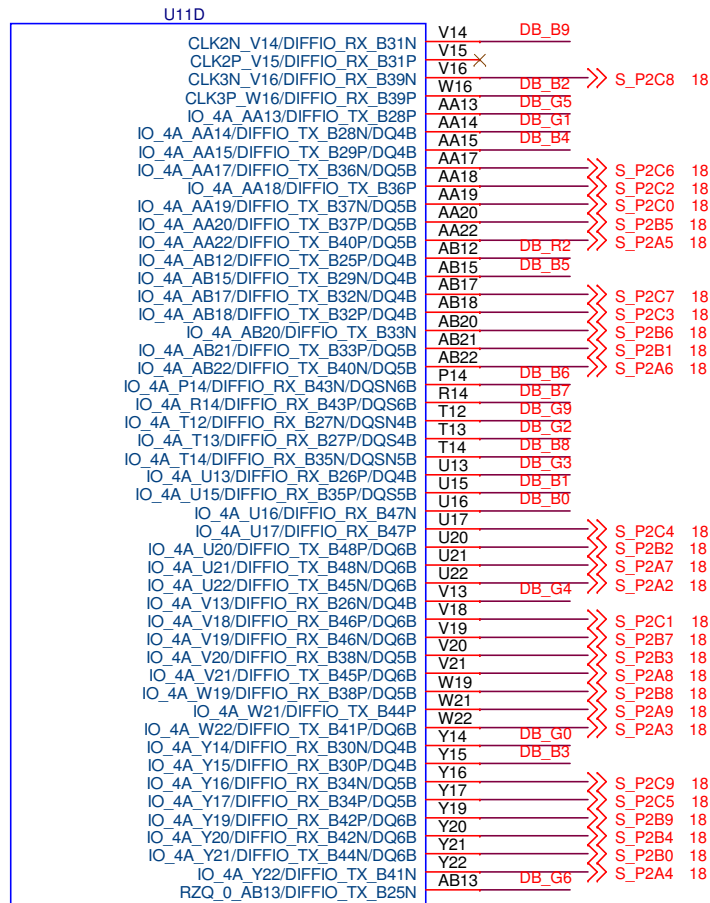
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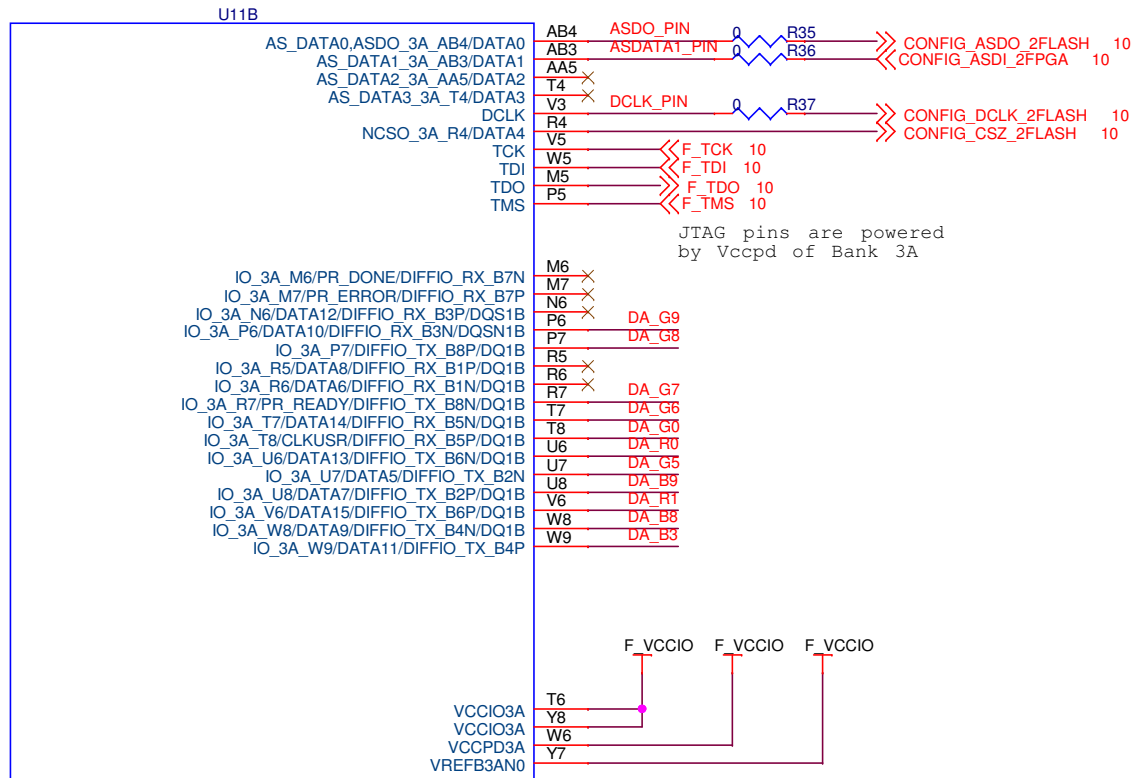
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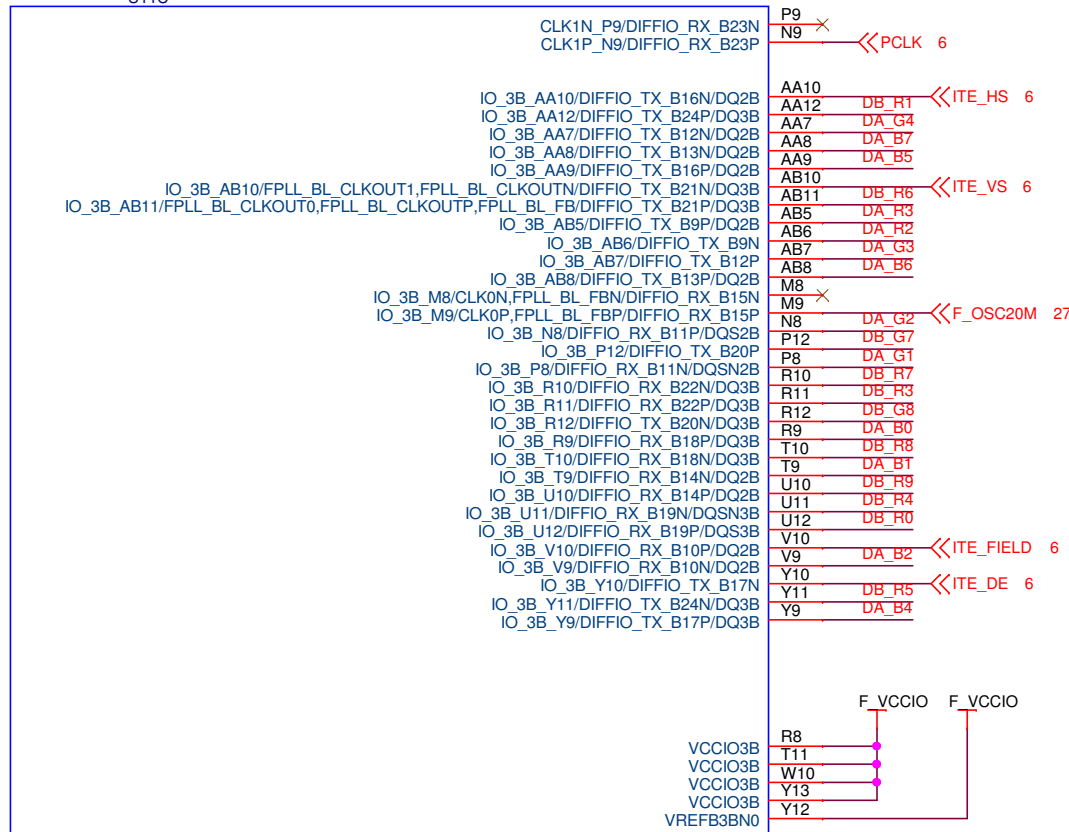
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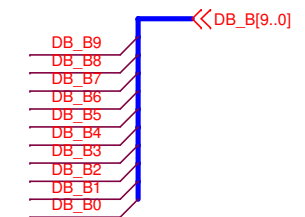
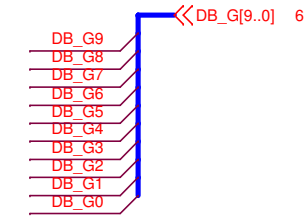
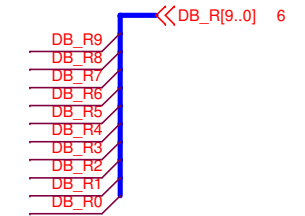
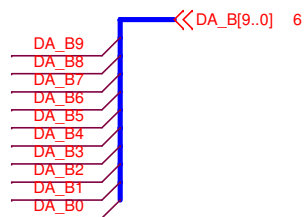
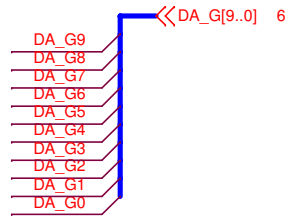
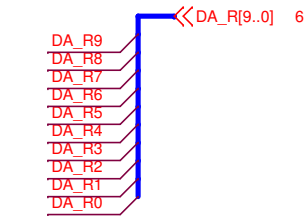
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FPGA Bank 2A, 3A, 3B, 4A

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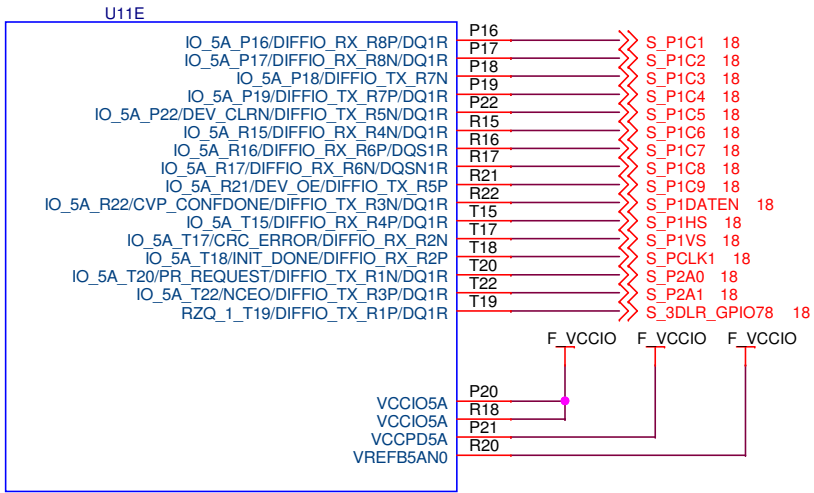
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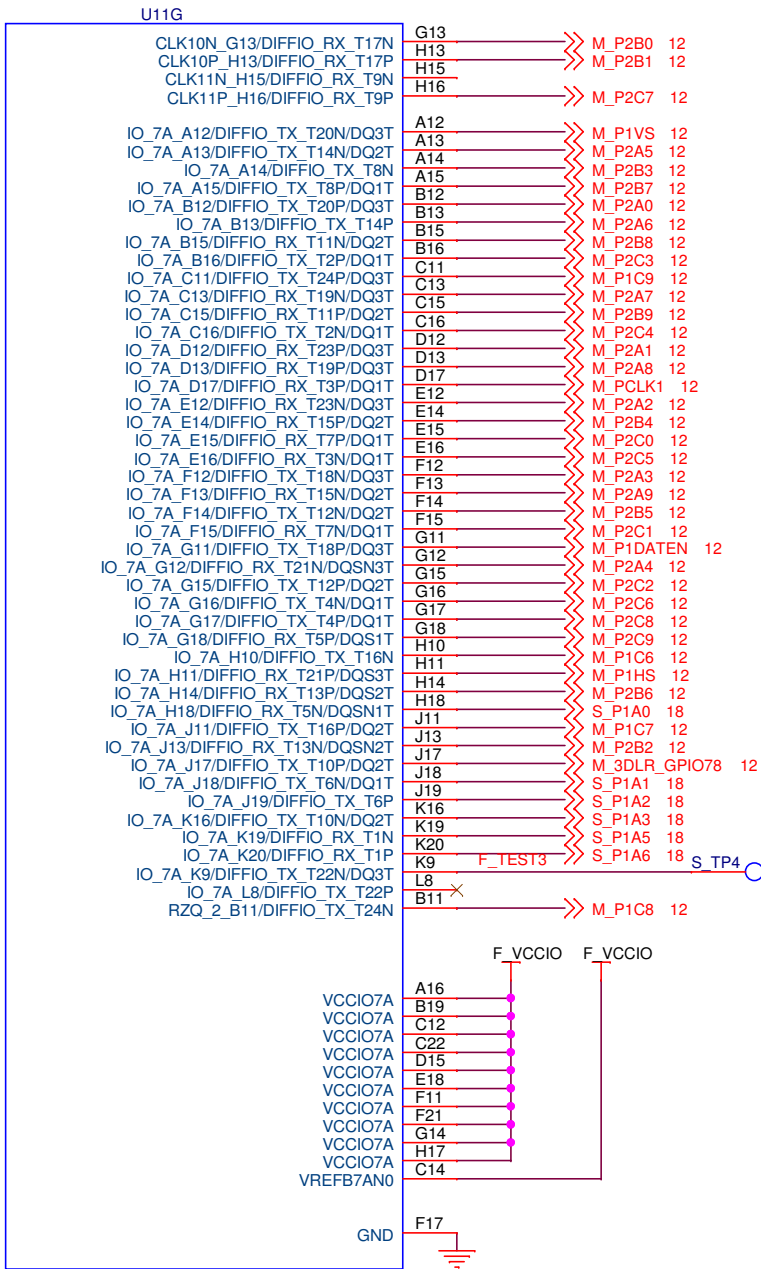
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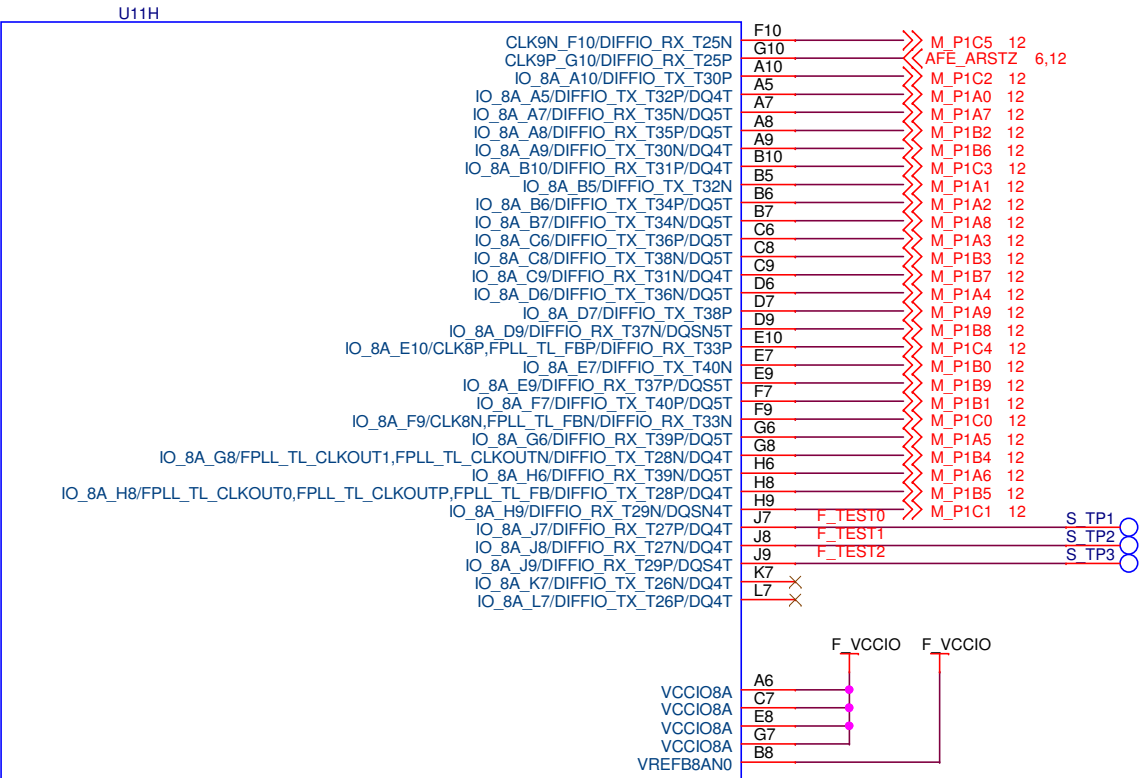
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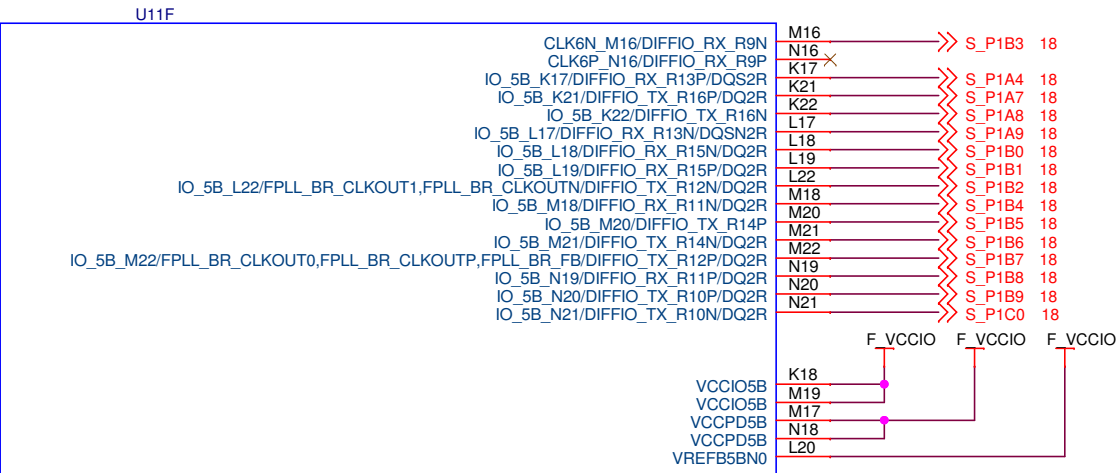
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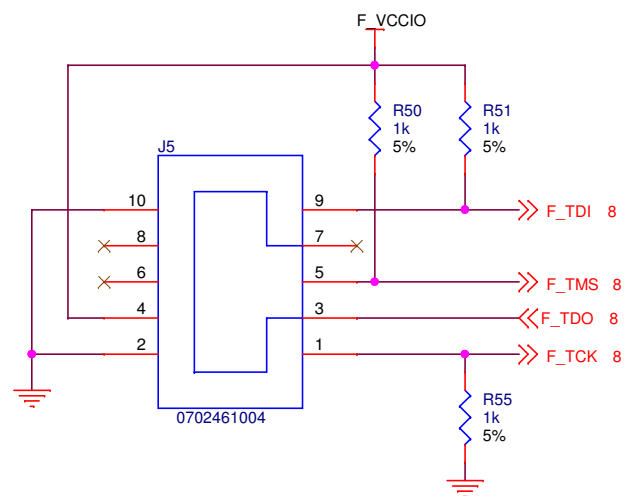
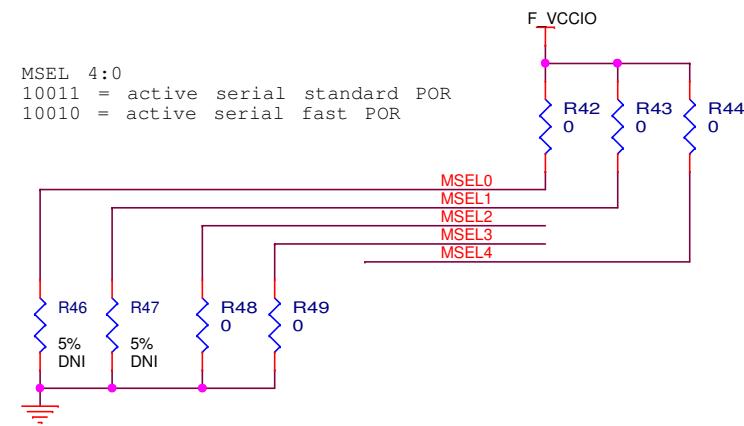
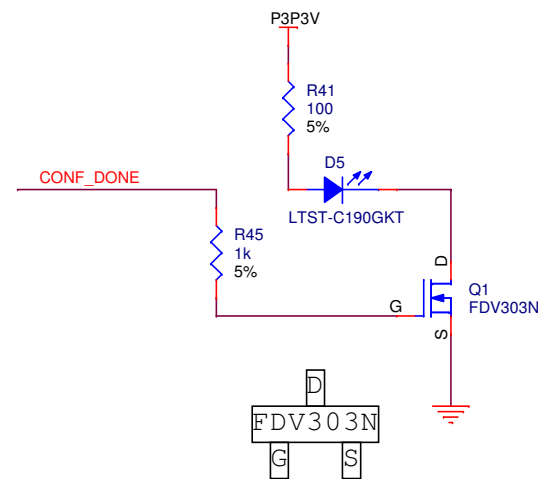
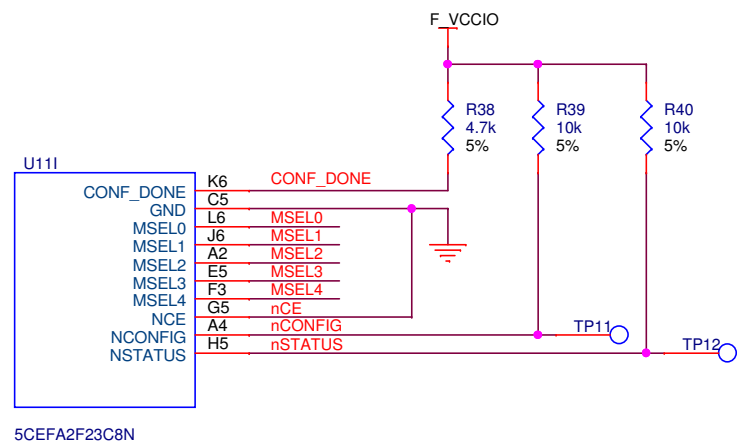


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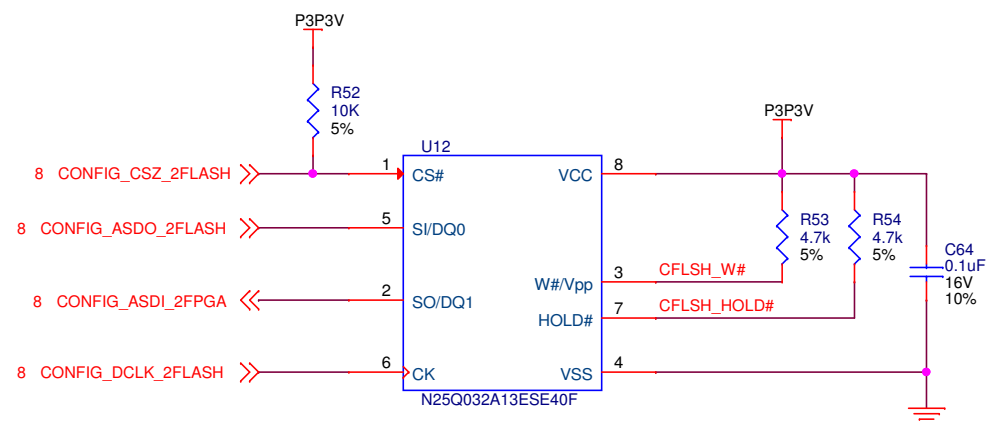


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FPGA Bank 5A, 5B, 7A, 8A



Altera's USB ByteBlaster Connector



Use Altera's "Serial loader" option to update flash thru the FPGA JTAG port with Byteblaster cable

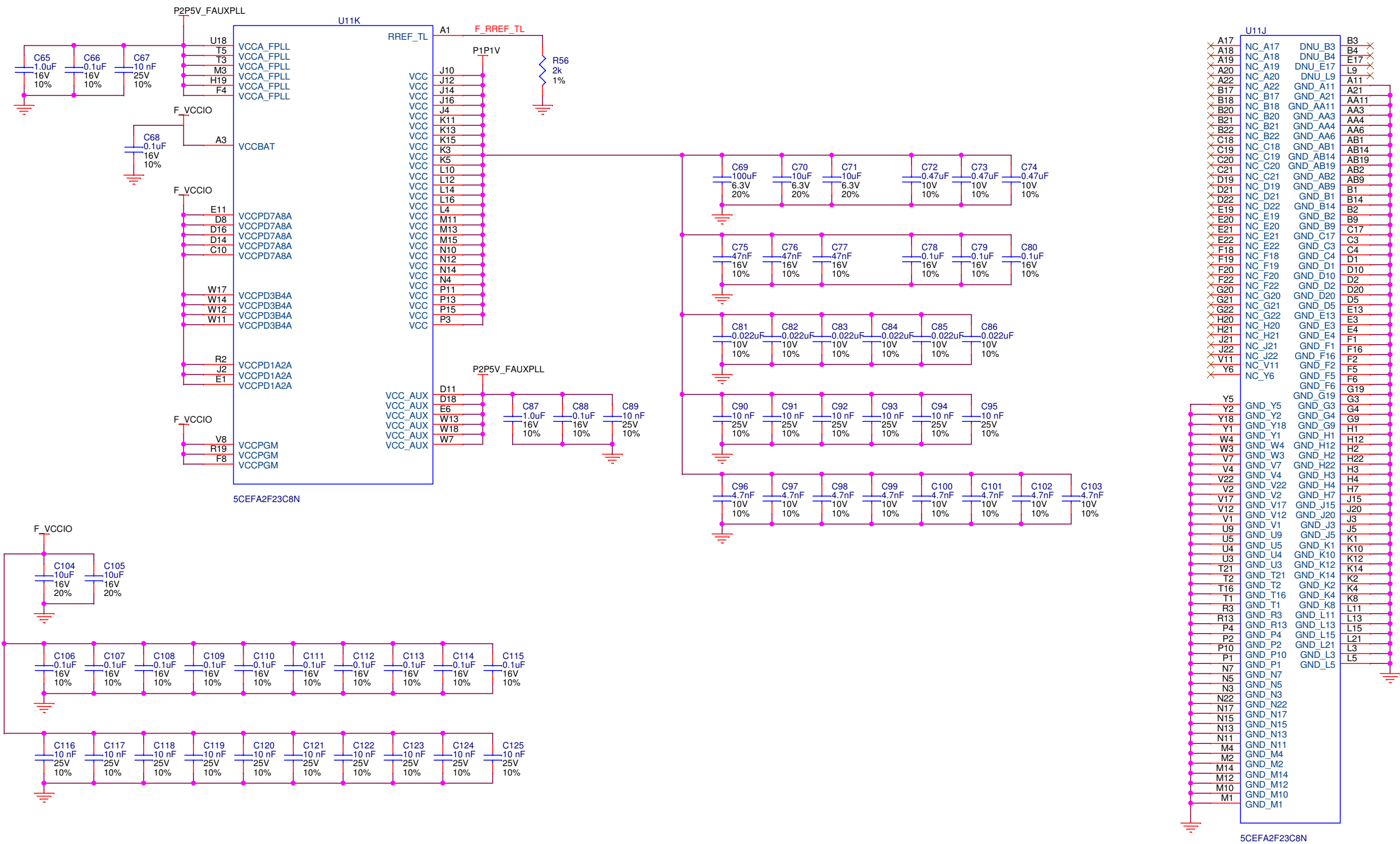
## FPGA Configuration

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FPGA Pwr/Gnd

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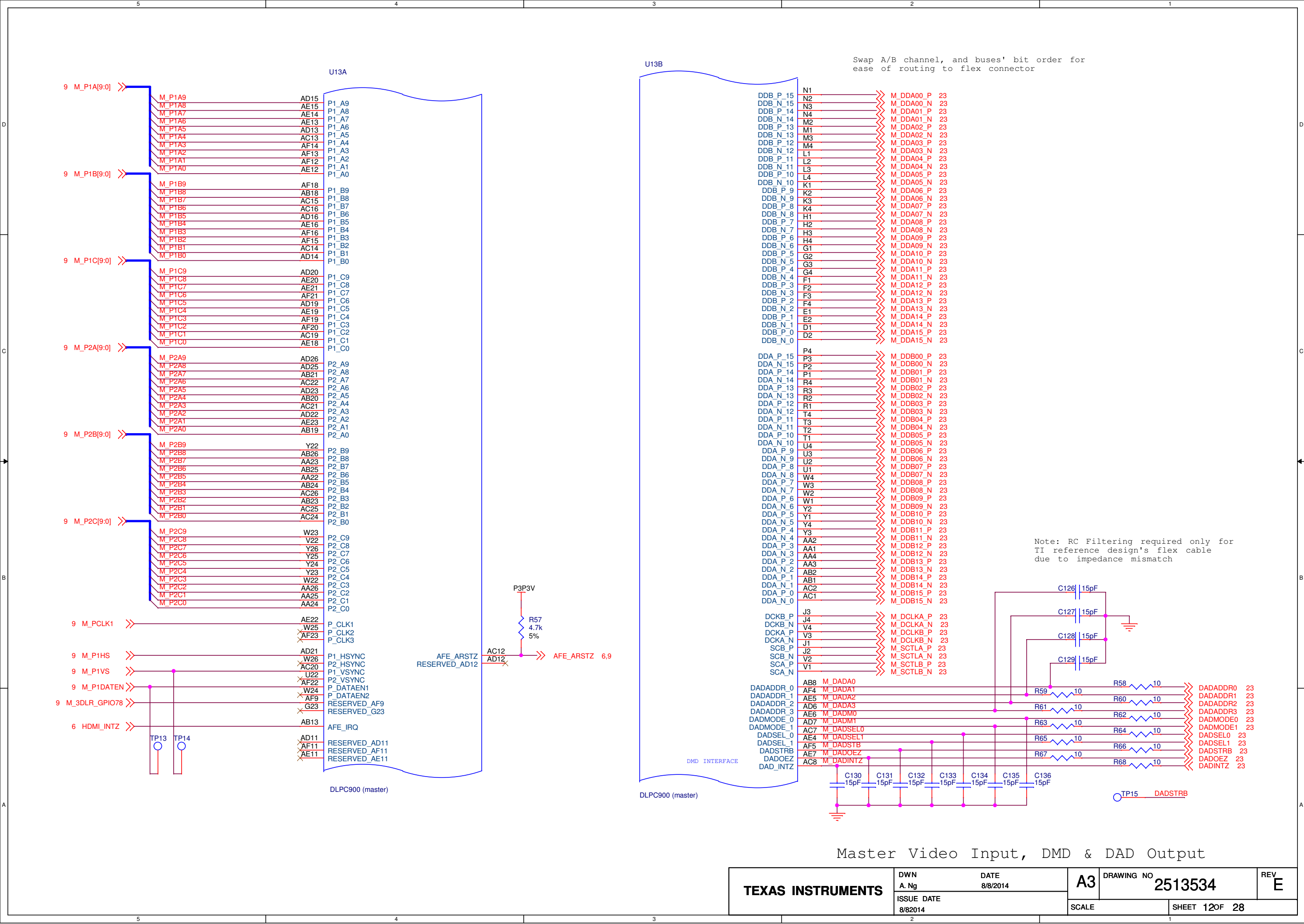
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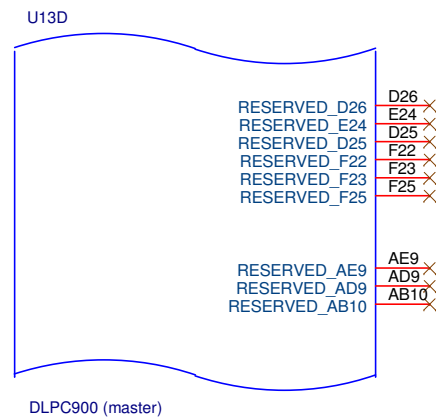
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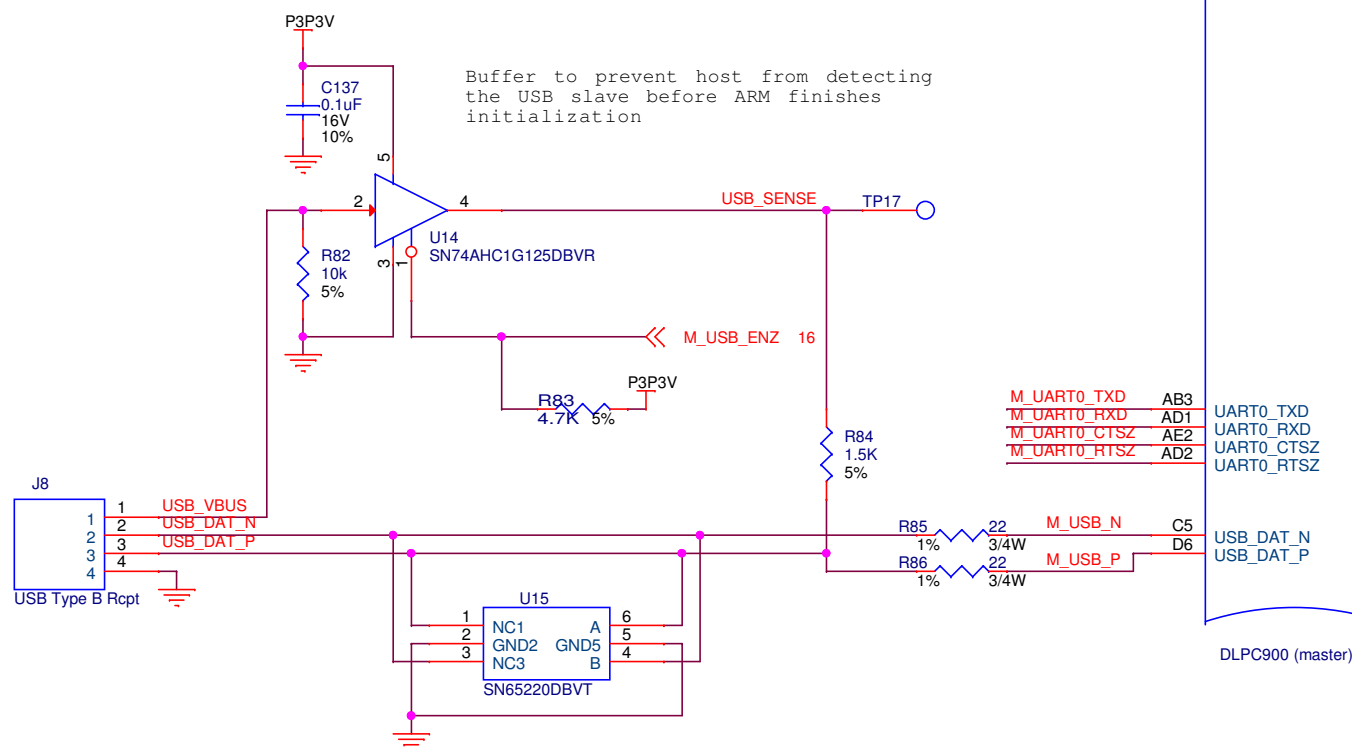
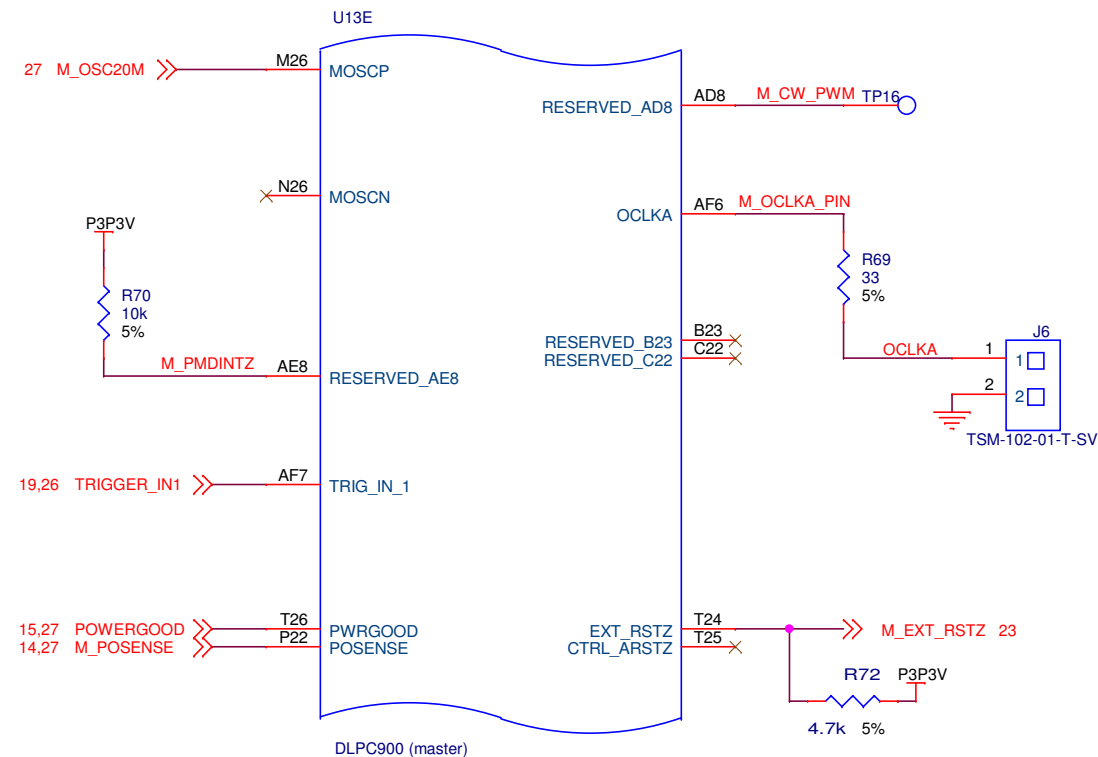
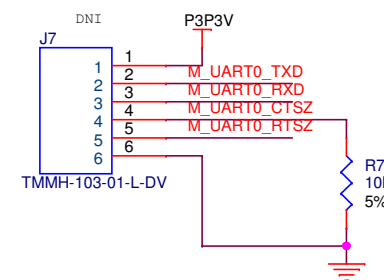
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UART debug message port,  
not needed for production



Master Controller SSP0, UART0, USB, Reset, OSC

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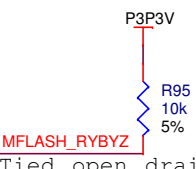
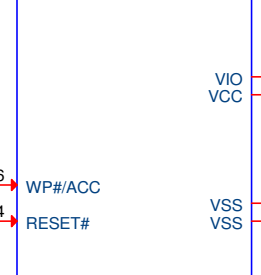
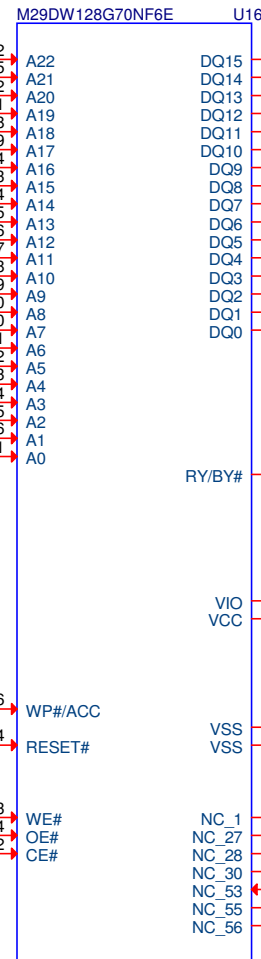
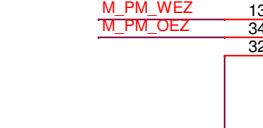
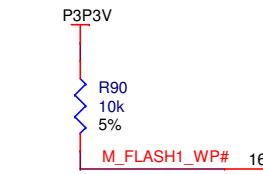
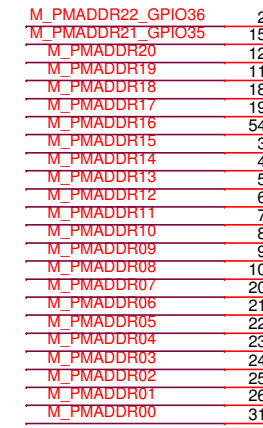
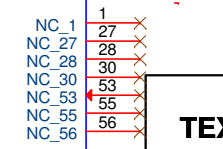
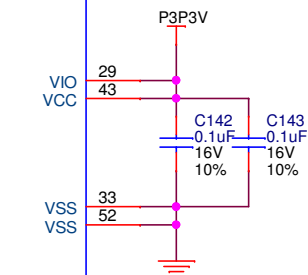
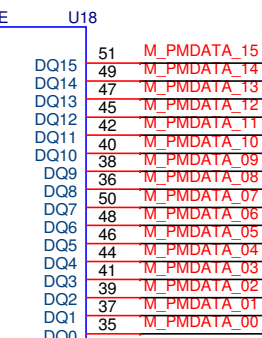
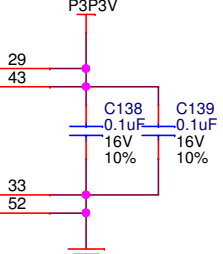
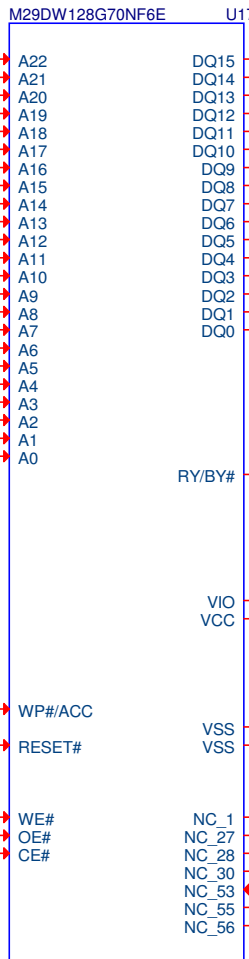
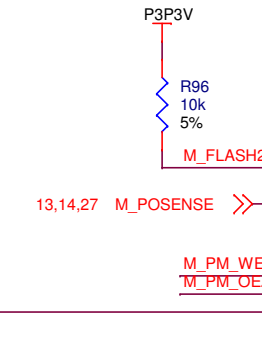
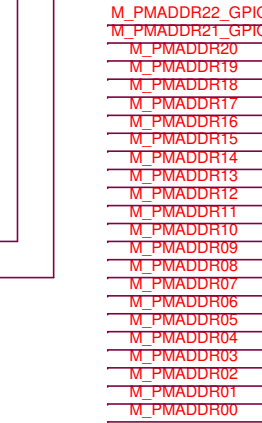
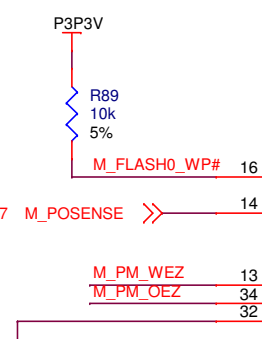
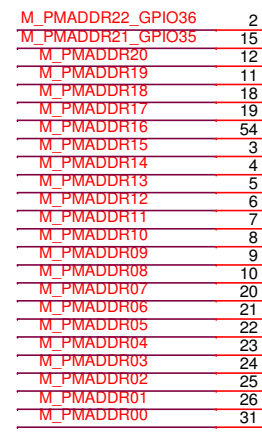
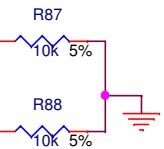
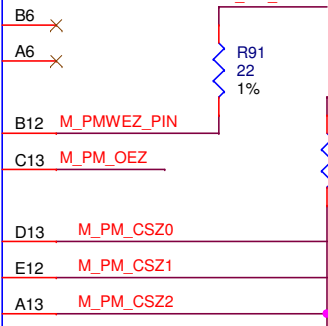
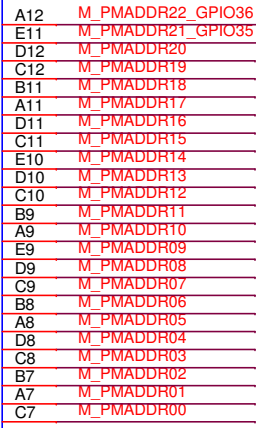
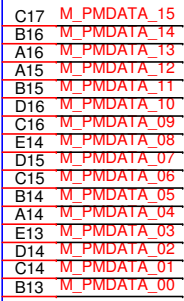
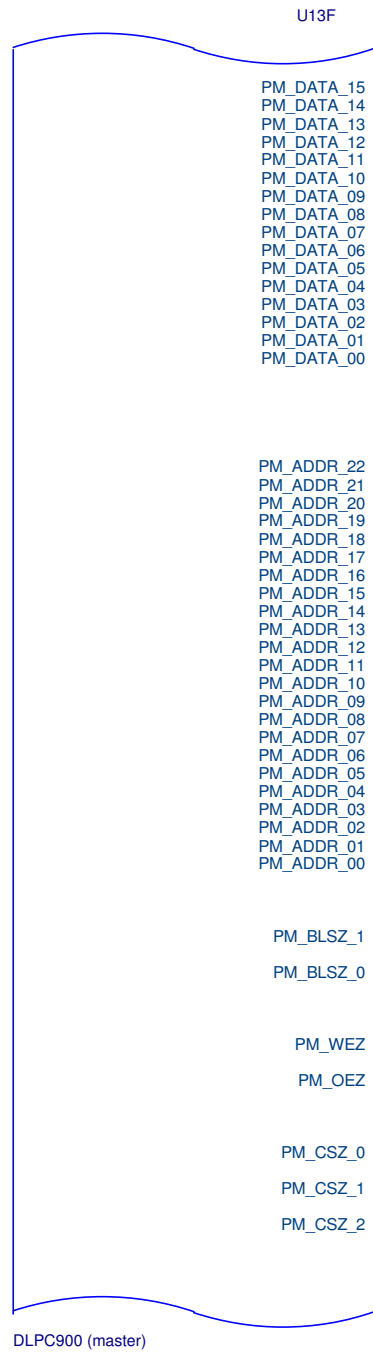
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Refer to the DLPC900 datasheet for other memory configurations.

# Master Controller Flash Interface

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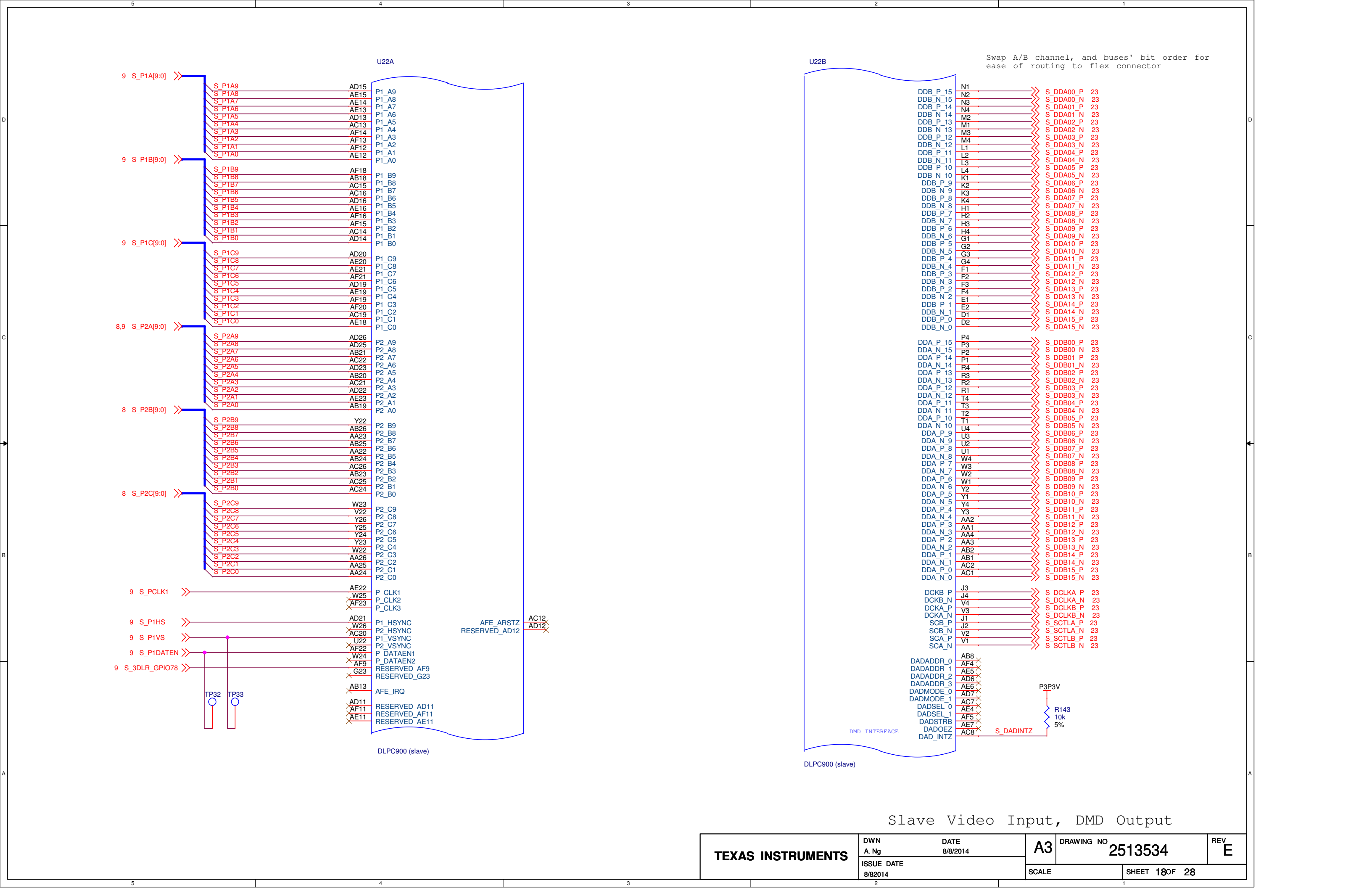
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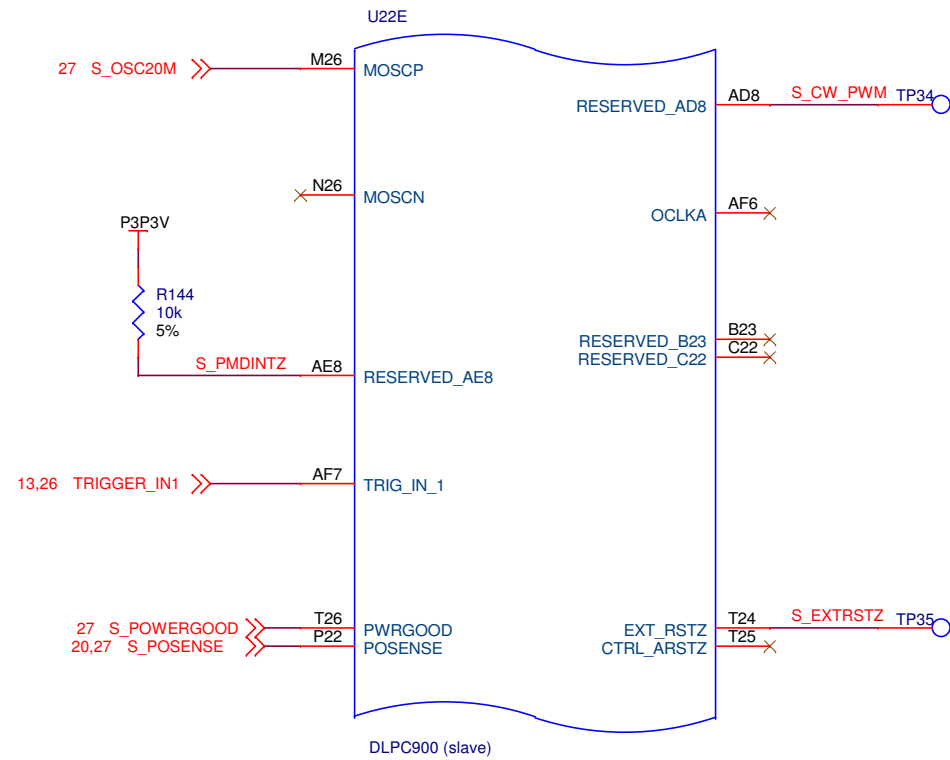
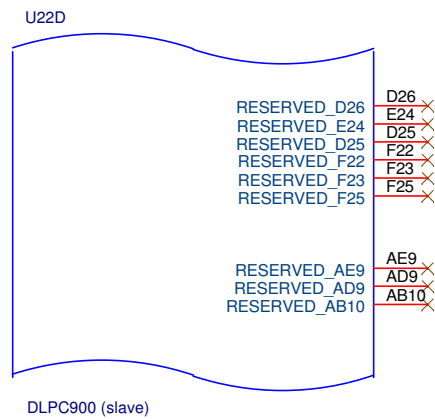




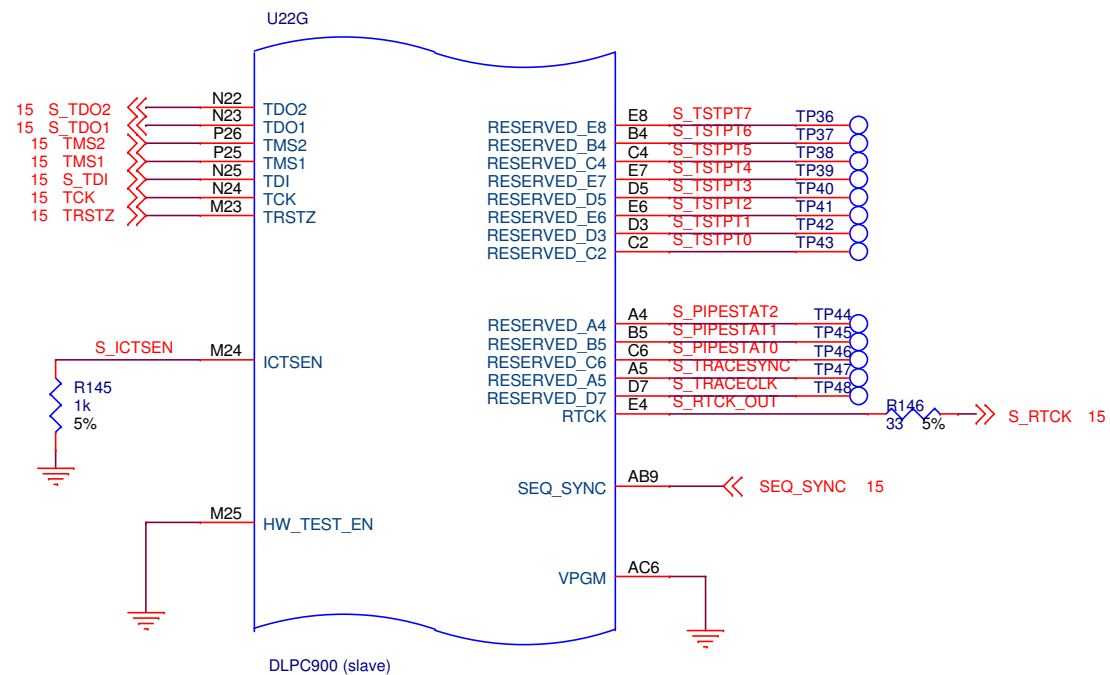
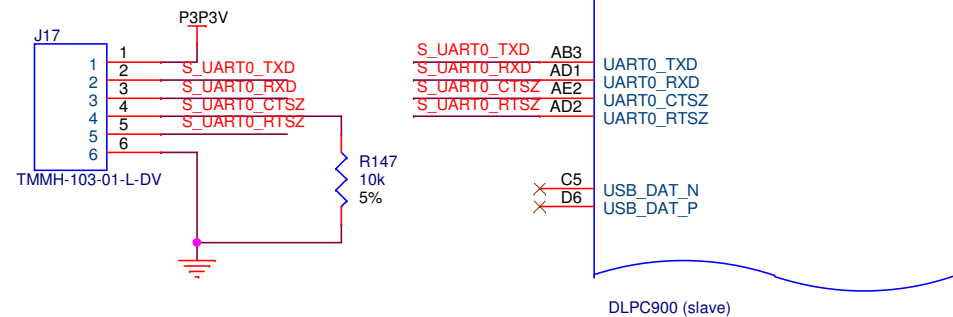




Slave Video Input, DMD Output



UART debug message port,  
not needed for production



Slave Controller Reset, OSC, JTAG, UART0, SSP Port

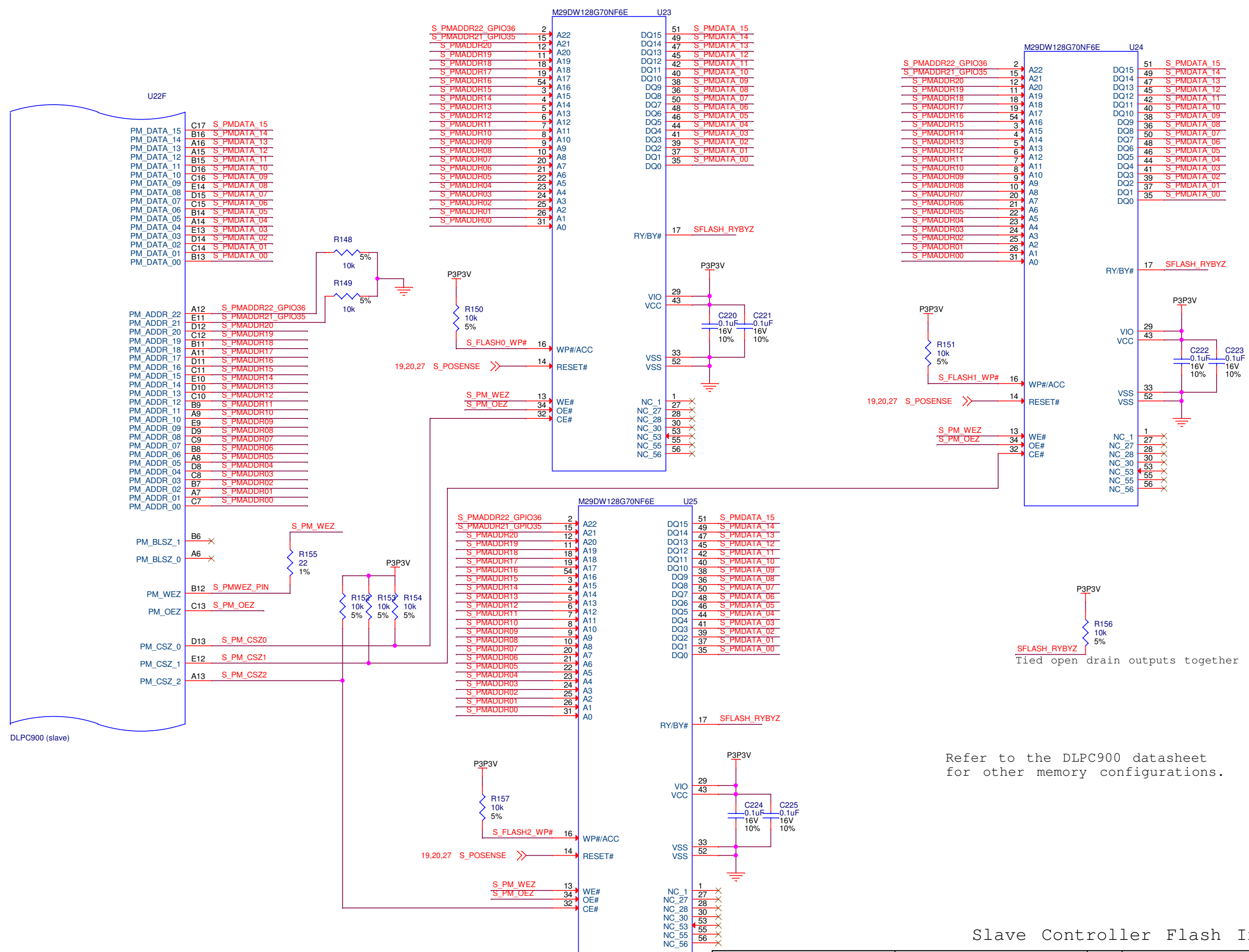
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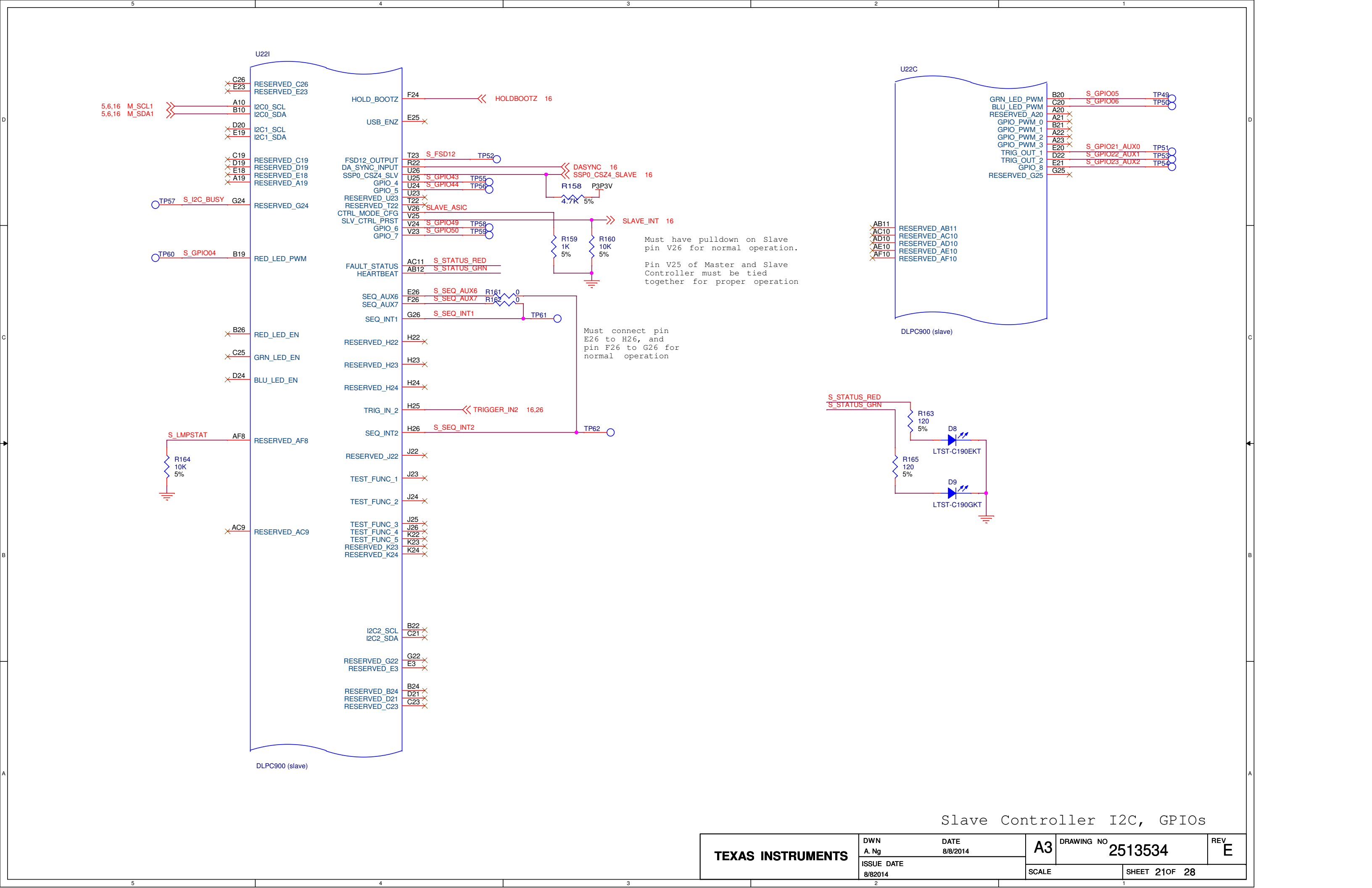
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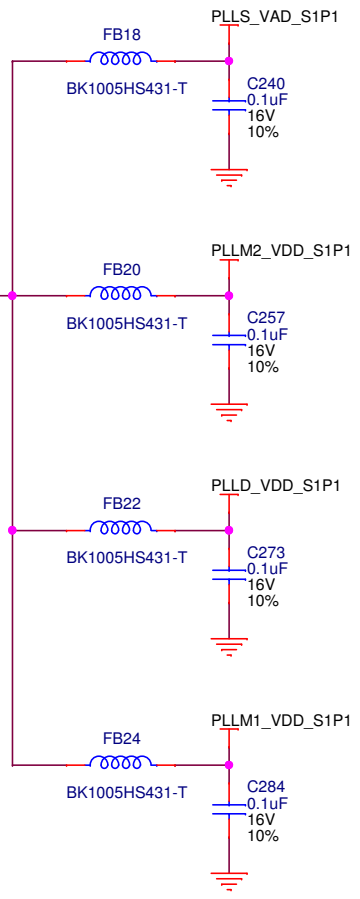
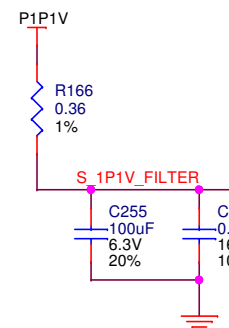
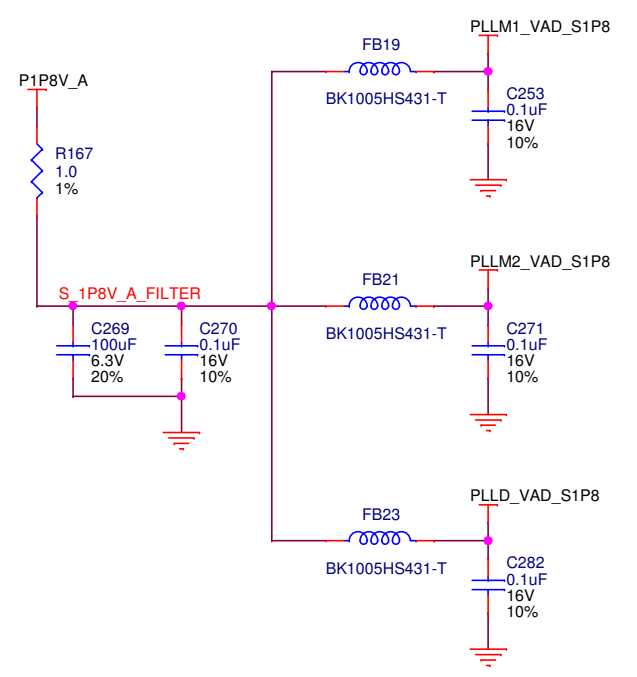
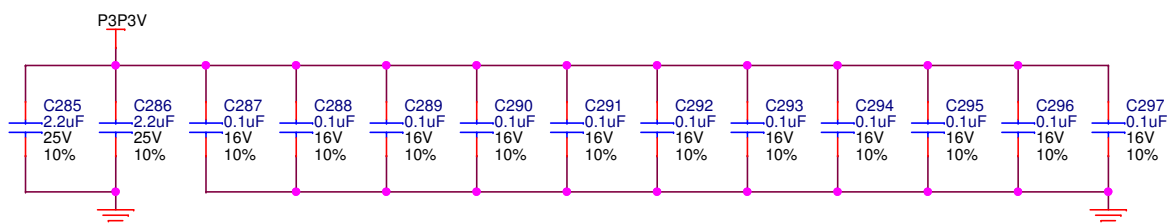
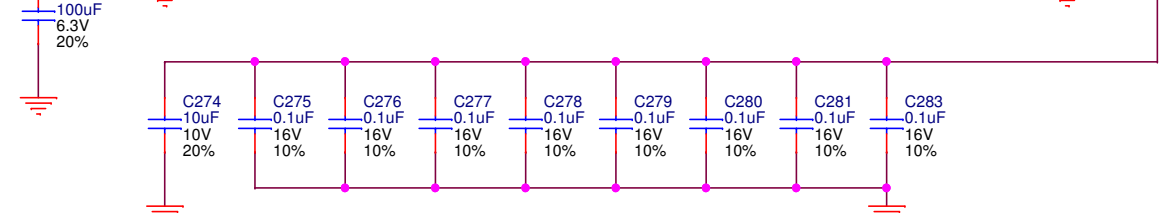
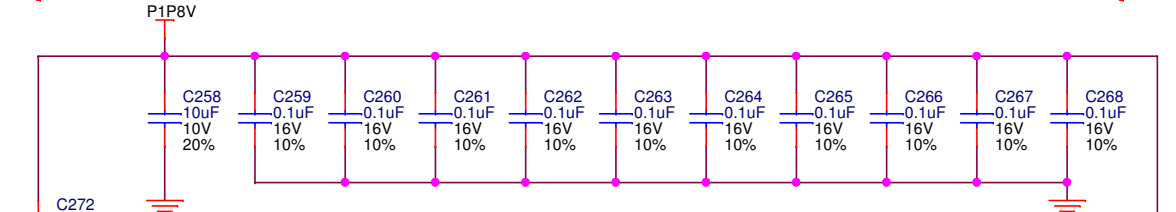
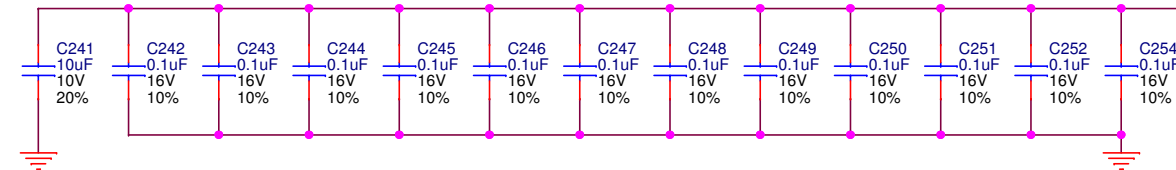
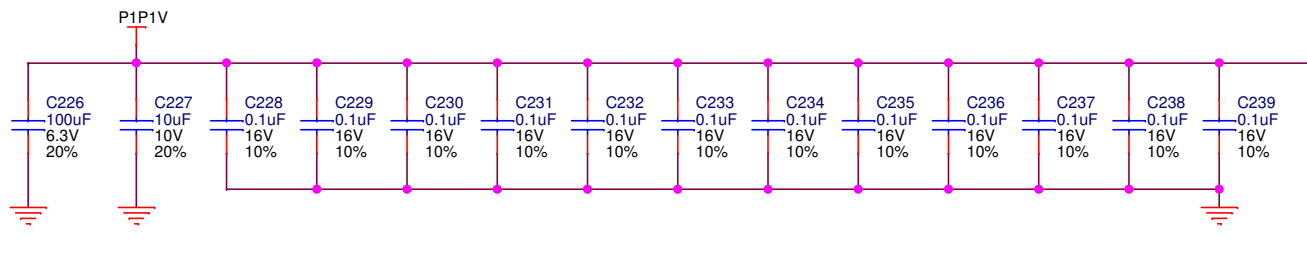
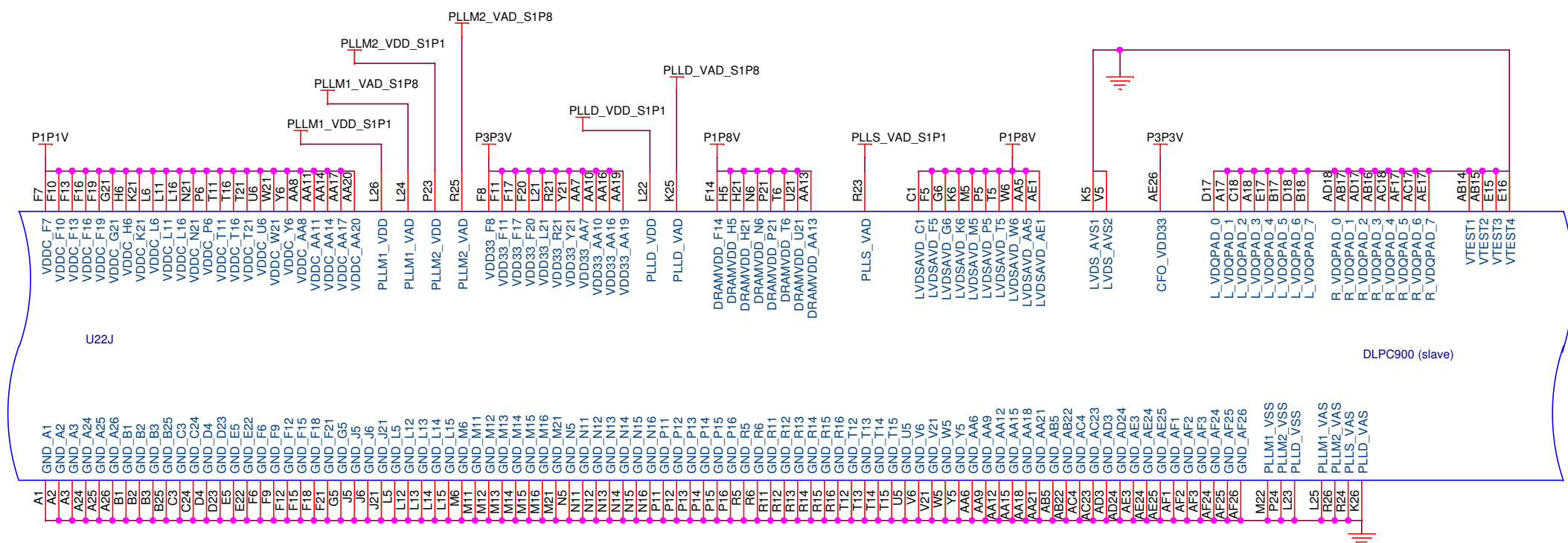
Refer to the DLPC900 datasheet for other memory configurations.

### Slave Controller Flash Interface

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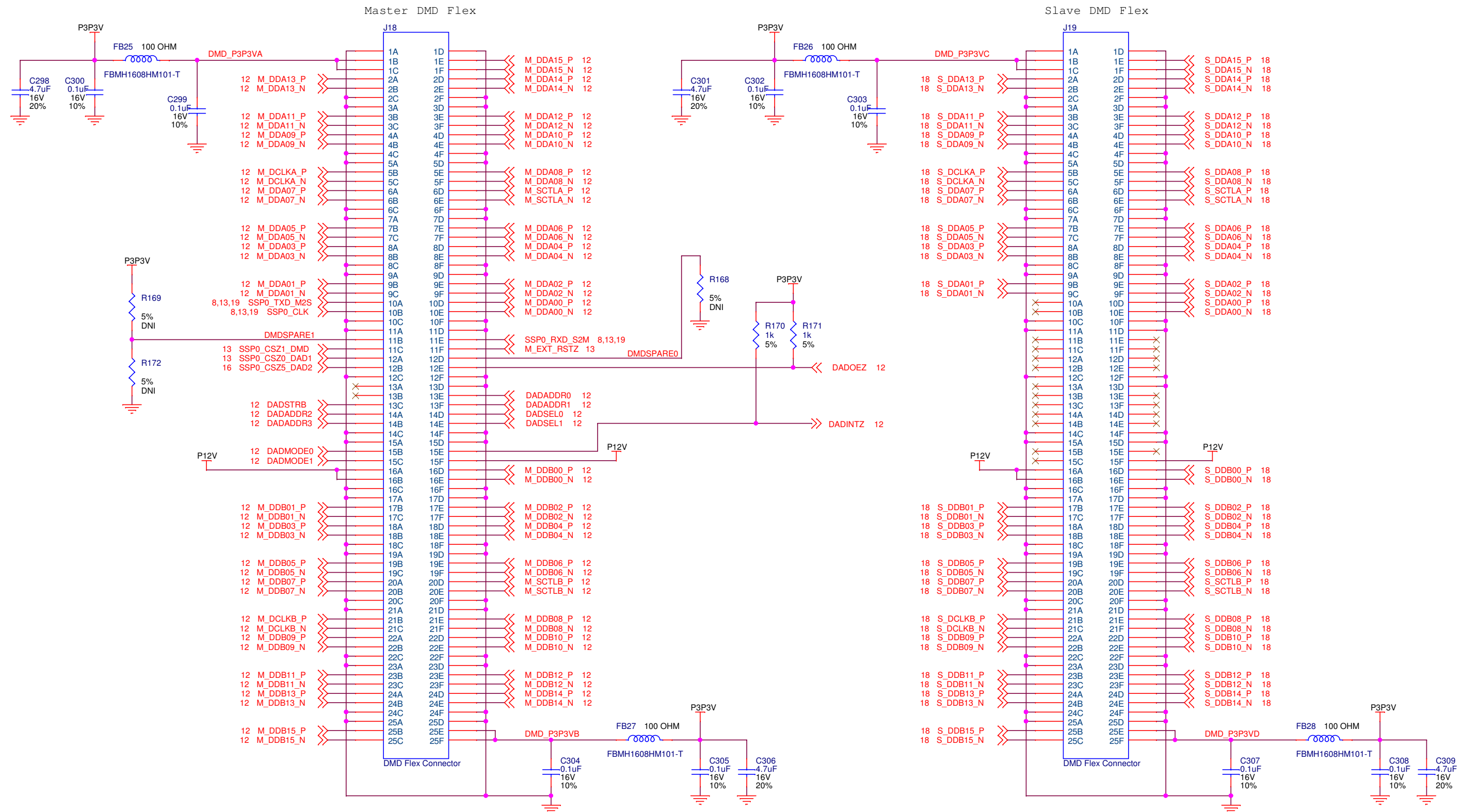


Slave Controller I2C, GPIOs

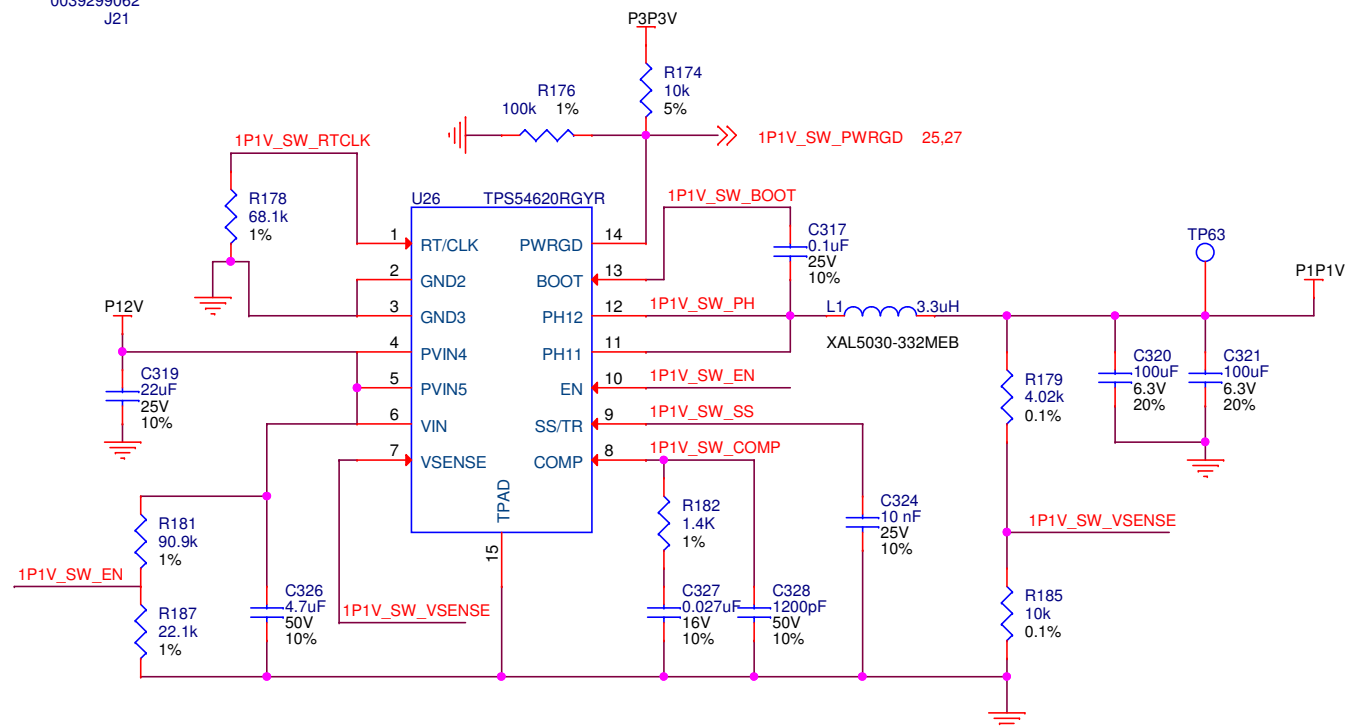
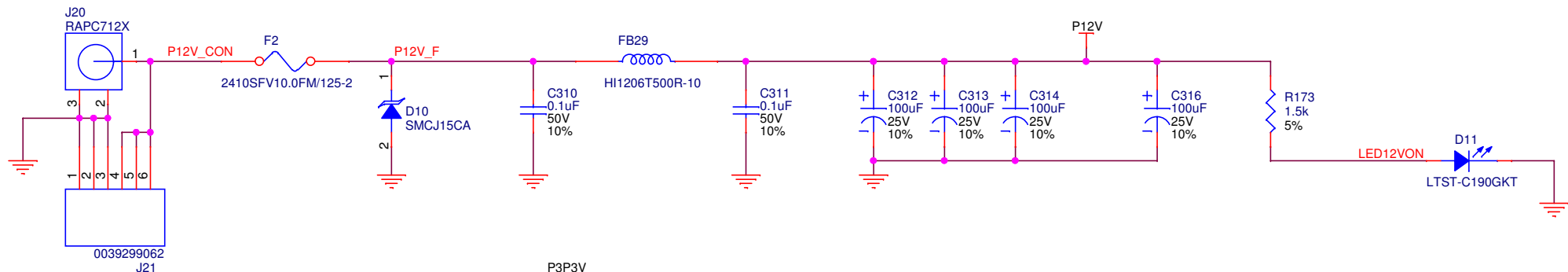


Slave Controller Pwr Gnd

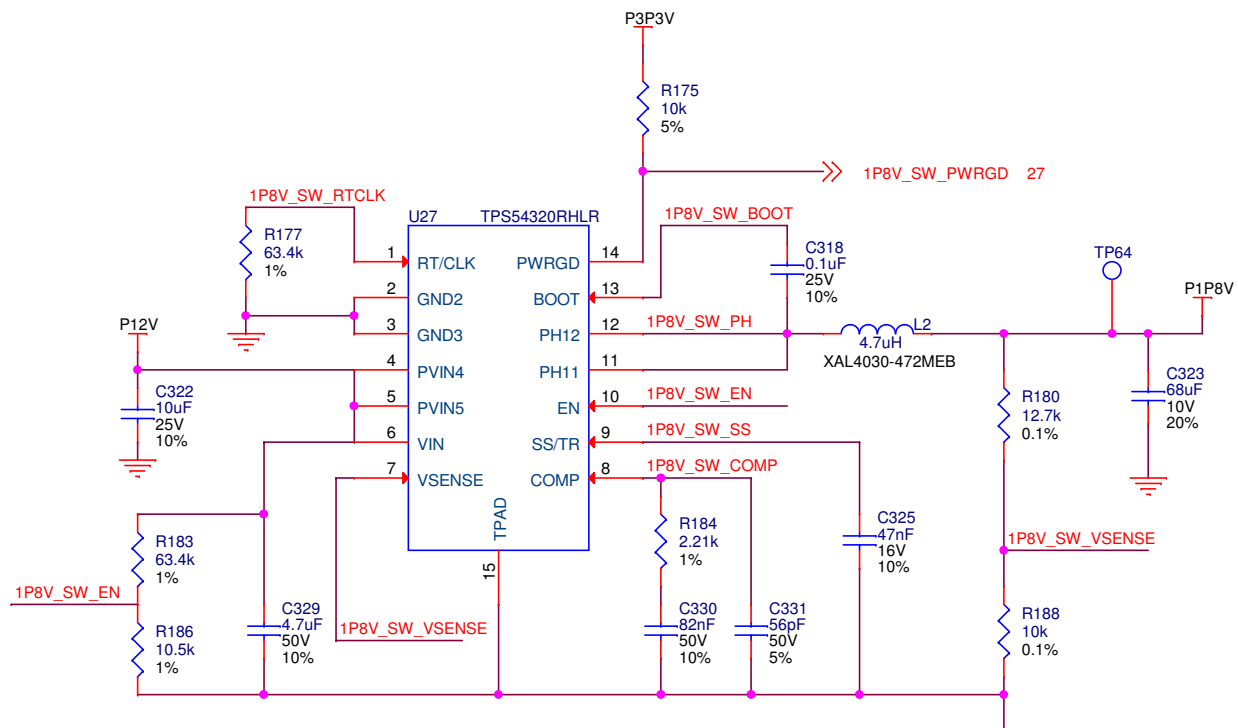
TI's EVM reference design has flex's electrical contact located on the PCB's top (component) side



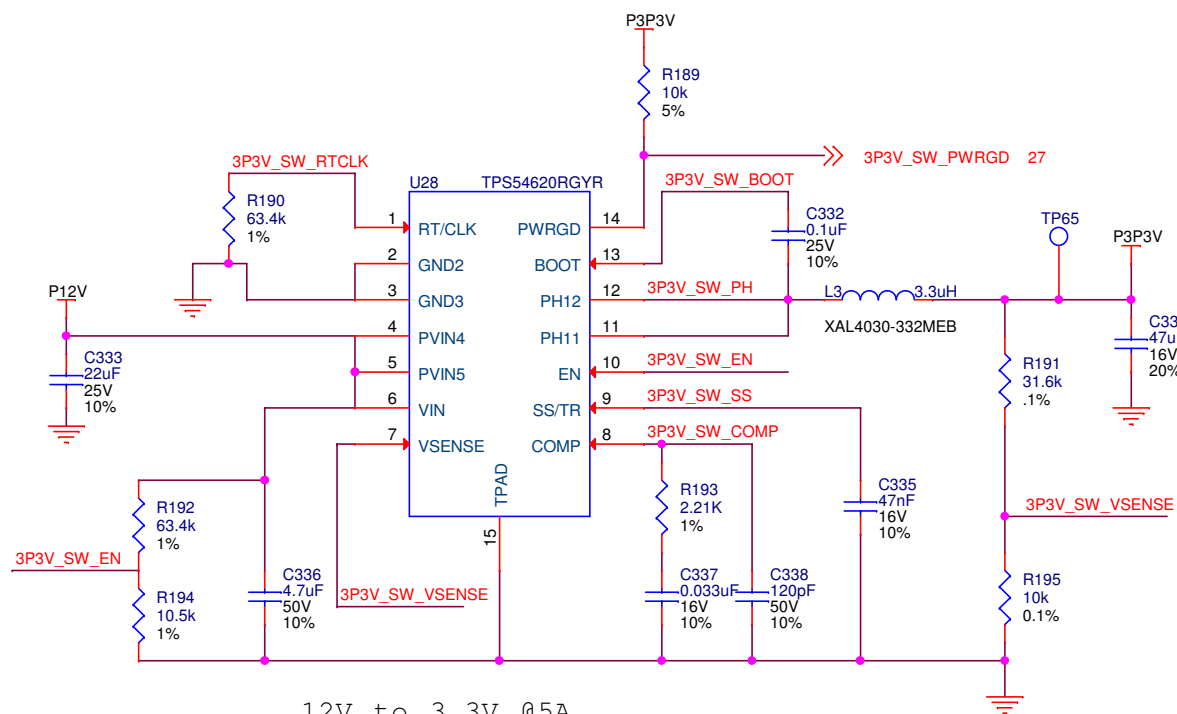
DMD Master/Slave Flex Connector



12V to 1.12V @6A  
Switching Freq ~ 700KHz  
Vstart/stop ~ 6.08V/5.57V  
SS ~ 3.5ms



12V to 1.8V @3A  
Switching Freq ~ 750KHz  
Vstart/stop ~ 8.44V/7.95V  
SS ~ 15ms



12V to 3.3V @5A  
Switching Freq ~ 750KHz  
Vstart/stop ~ 8.44V/7.95V  
SS ~ 15ms

Power Generation 1.1V, 1.8V and 3.3V

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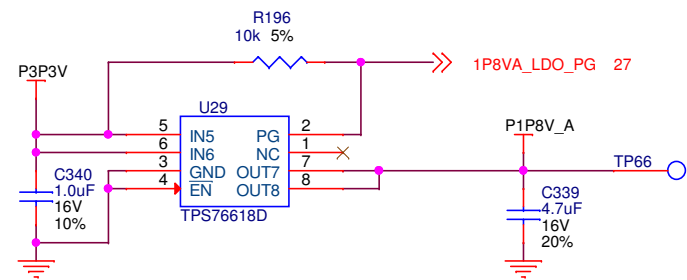
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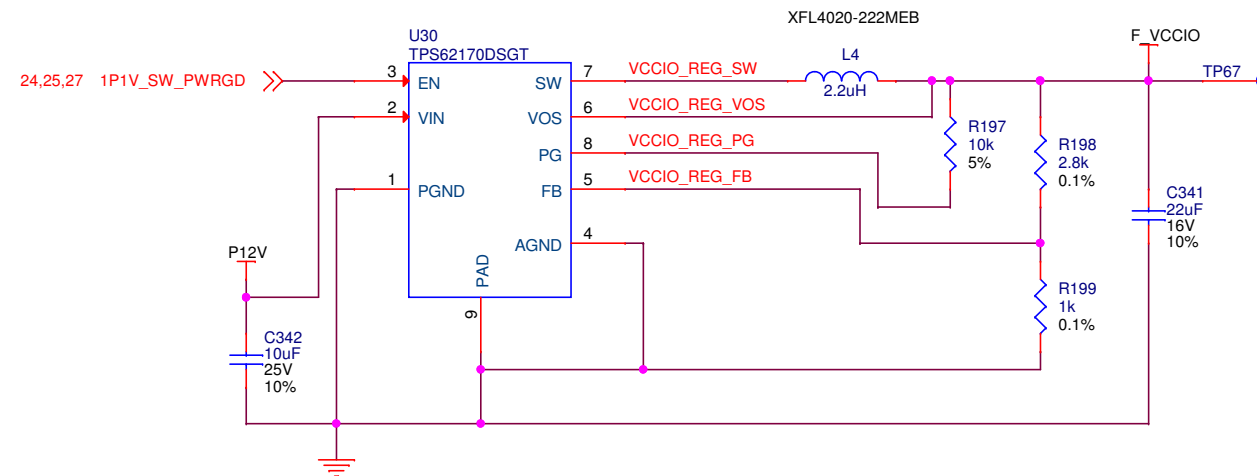
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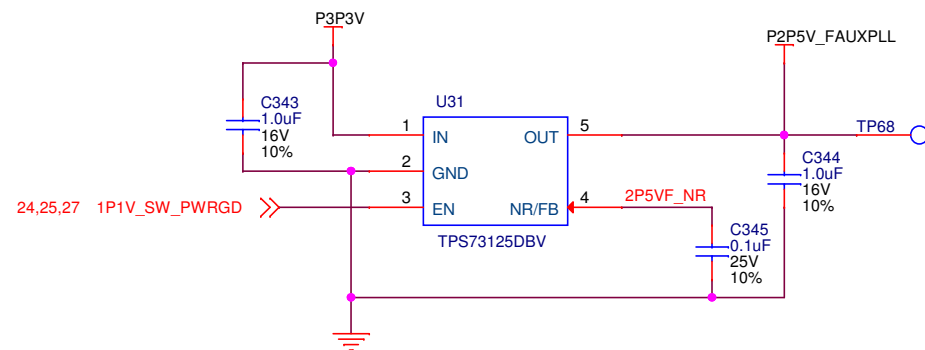
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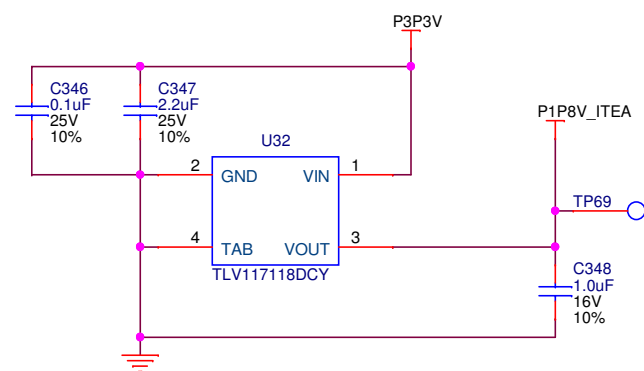
3.3V to 1.8V @250mA LDO  
for controller 1.8V analog



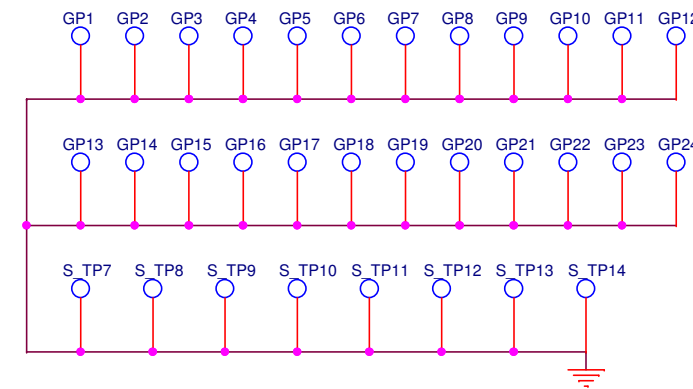
12V to 3V @500mA  
for FPGA Vccio



3.3V to 2.5V @150mA LDO  
for FPGA 2.5V AUX/PLL power



3.3V to 1.8V @1A LDO  
for HDMI Rx 1.8V analog



Distribute ground vias around PCB

Power Generation FPGA's VCCIO, 1.8V & 2.5V LDOs

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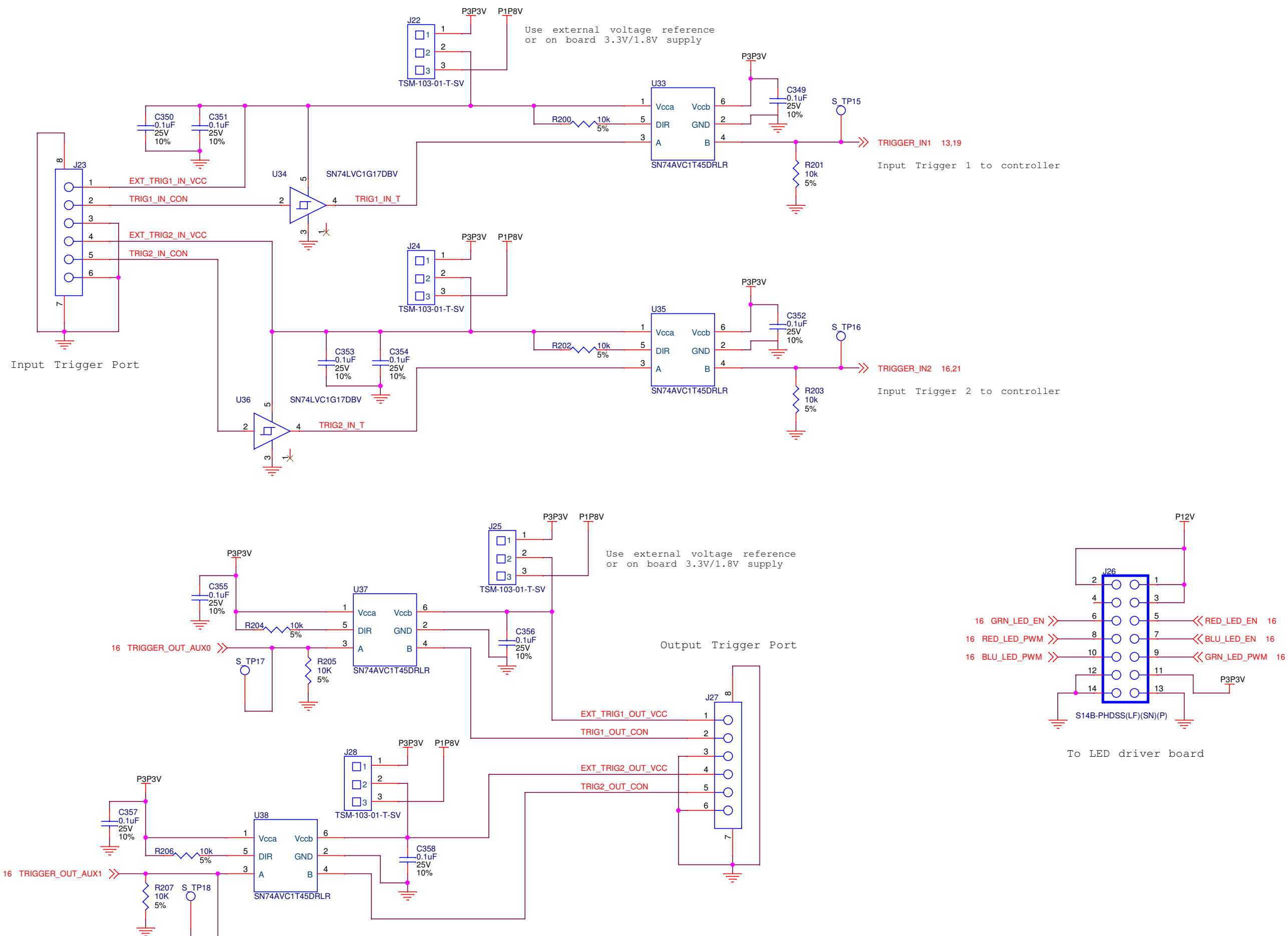
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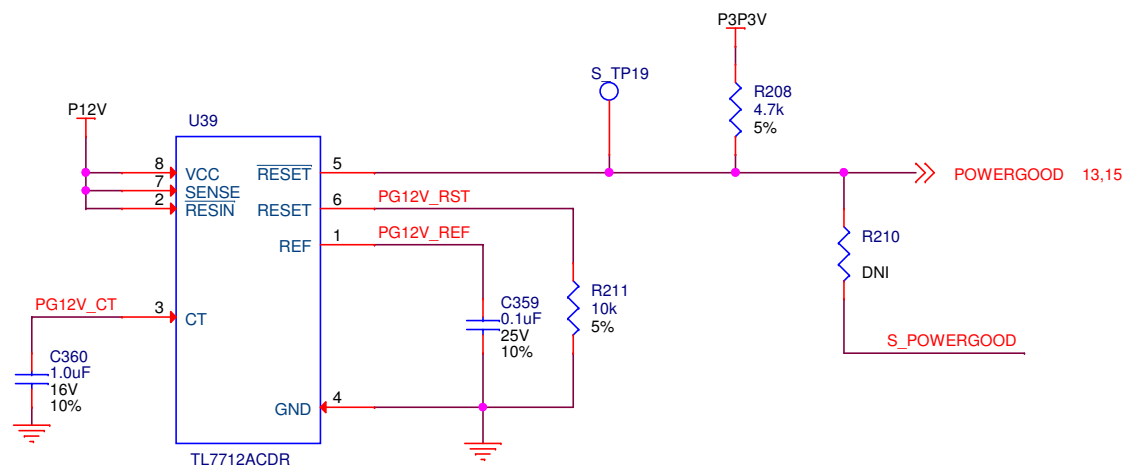
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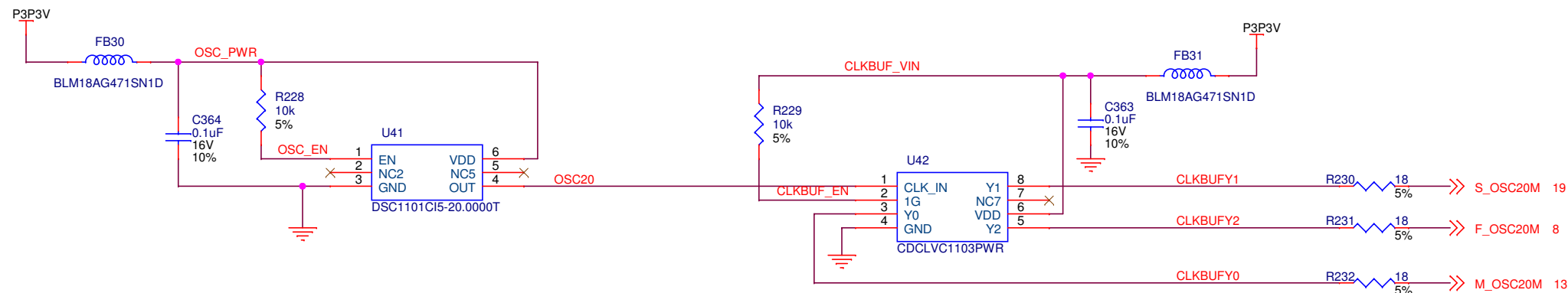
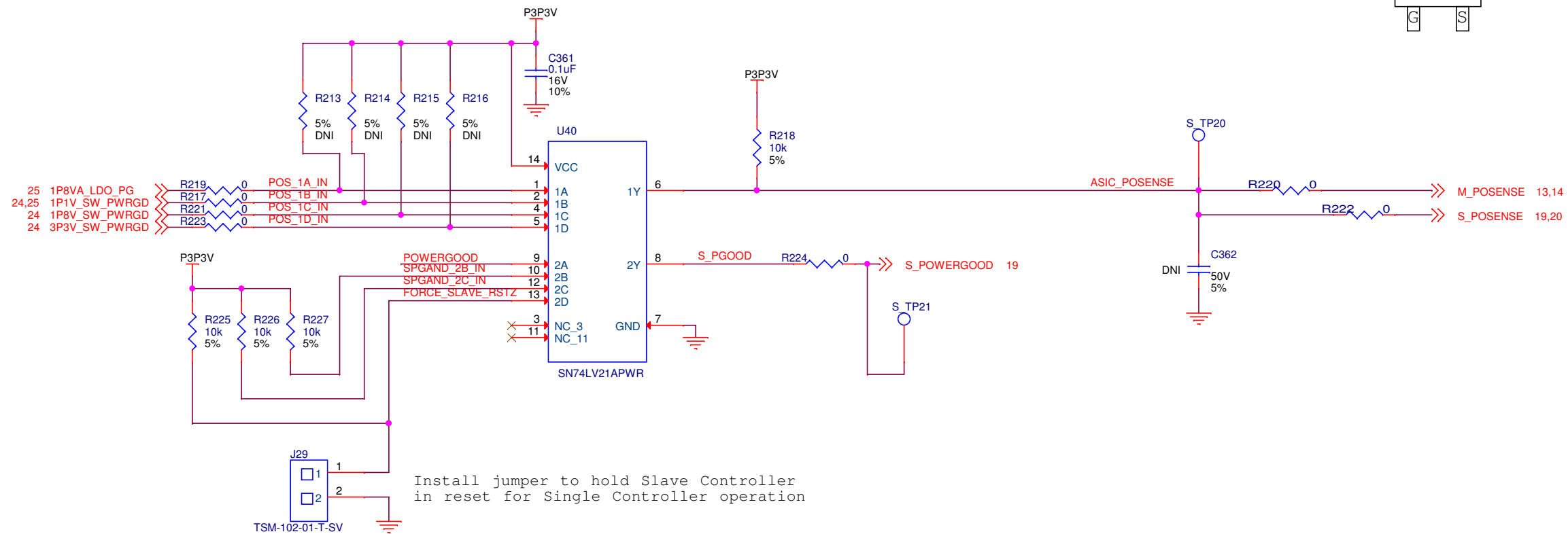
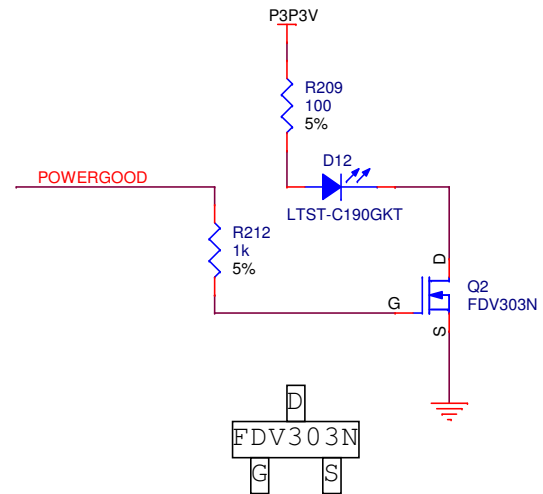


Input/Output Trigger and LED Driver Interface



Per controller spec (Fig. 3), POWERGOOD has no impact on operation for 60ms after rising edge of POSENSE. In other words, during power up, controller will ignore the state of PG until the internal PLL is locked (require up to 60ms). Controller will then sample the PG input to begin normal operation.

During power down, POSENSE has to remain valid high for at least 500us after PG is deasserted to allow controller to complete the DMD parking procedure. The 500+ uF input caps on 12V would ensure the power monitor to trip at ~11V to deassert PG while keeping regulators operational to maintain POSENSE for > 500us.



Generate Powergood, POSENSE, Clocks

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REVISION HISTORY

Rev A

- PAGES - ALL
- initial rev

Rev B

- PAGE 27
- new part for C360
- PAGE 26
- relocated S\_TP17 and S\_TP18
- PAGE 24
- new part for R179
  - removed C315, bulk cap not needed
- PAGE 25
- new part for L4
- PAGE 10
- new part for U12

Rev C

- PAGES for U13 & U22
- update pin name to match datasheet
- PAGE 15
- add comments for usage of R117 & R118

Rev D

- Remove references to DLPC910

Rev E

- Updated U7

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